

主机外观图

机型名: V9

上市时间: 2012 年 9 月



产品定义

产品概述

整机外形	PDA	通信制式	WCDMA单模单卡		
SIM卡槽数量	单卡槽	整机长宽厚尺寸	133.9X67.3X10.8	整机重量(含电池)	163g
硬件平台	Nvidia AP33 Infineon XMM626				

硬件规格

类型	项目	描述
显示屏	尺寸(英寸)	4.5"
	分辨率	540*960
	材质	TFT
	色彩数	16M
	连接方式	ZIF
	触摸	电容触摸
	多点触摸	多点
前摄像头	像素	30万
	变焦类型	定焦FF
	连接方式	SMT
后摄像头	像素	500万
	变焦类型	自动变焦AF
	连接方式	B-T-B
电池	电池容量	1800mAh
	电池类型	锂离子
声音	耳机立体声	Yes
	免提	支持
	喇叭	支持

	喇叭尺寸规格	单喇叭
存 储	T卡卡槽	不支持
	T卡最大容量	32GB
	ROM	4GB
	RAM	1GB
按 键	主键盘板类型	与触屏集成
	触感按键	支持
	按键LED数量	1
	按键LED颜色	白
FM	FM天线	不支持
	FM外放	不支持
无线通信	蓝牙	支持蓝牙2.0
	NFC	不支持
	GPS	支持
	WiFi	支持802.11g/b/n
灯 光	闪光灯	单LED
	手电筒	不支持
	七彩灯	不支持
	紫外验钞灯	不支持
TV	模拟电视	不支持
	数字电视	不支持
	TV-OUT	不支持
传 感 器	环境光传感器	支持
	接近传感器	支持
	重力传感器	支持

传感器	加速度传感器	支持
	E-compass	支持
	陀螺仪	不支持
接口	耳机接口	3.5mm耳机
	充电接口	Micro-USB
	USB接口	Micro-USB
	HDMI/MHL接口	不支持

拆装机注意事项

一、拆卸注意事项：

- 1.拆卸 FPC 组件时避免由于暴力拆卸造成主板或 FPC 组件破损。
- 2.在拆显示屏的时候注意需要前后四周加热二分钟，温度 120℃
- 3.主板上防静电胶带较多，安装时保证原位置焊盘不能裸露，以免造成静电损伤。
- 4.具有极性的元件在组装时要注意方向，不要装反。
5. 拆卸完显示屏必须清理前壳，显示屏的泡棉胶，如果前壳要重复使用必须更换泡棉胶
- 6.泡棉胶料号：TYC7812A271008

二、所需工具：

拨片、撬棍、塑料镊子、金属镊子、螺丝刀、手术刀



电烙铁



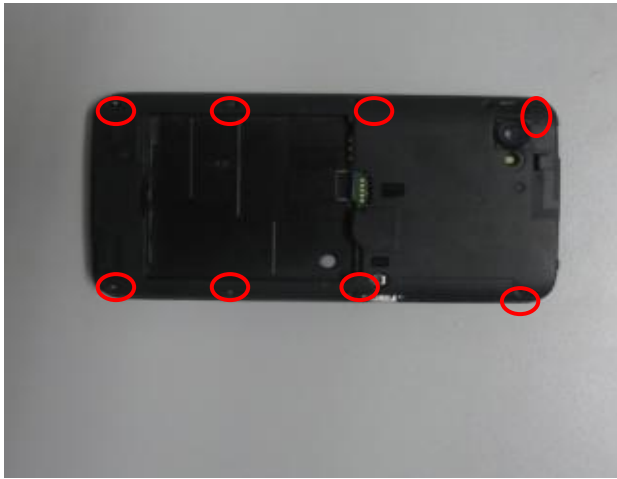
二、步骤:



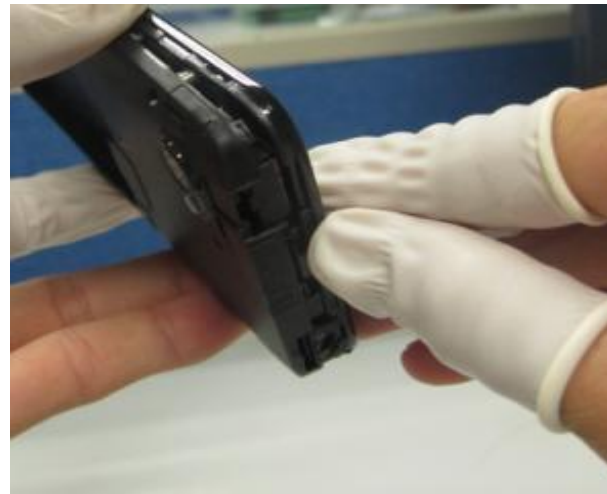
1.) 从左侧下方缺口处打开电池盖



2.) 取下电池



3.) 拧下 8 颗螺钉



4.) 从顶部拆下后壳组件



5) 拆开后壳的效果图 (妥善保管卡槽卡片装机务必装回原为)



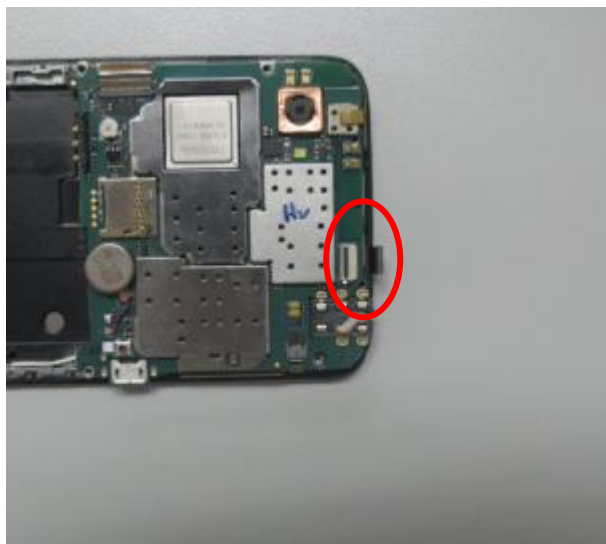
6) 用镊子拆下扬声器组件。



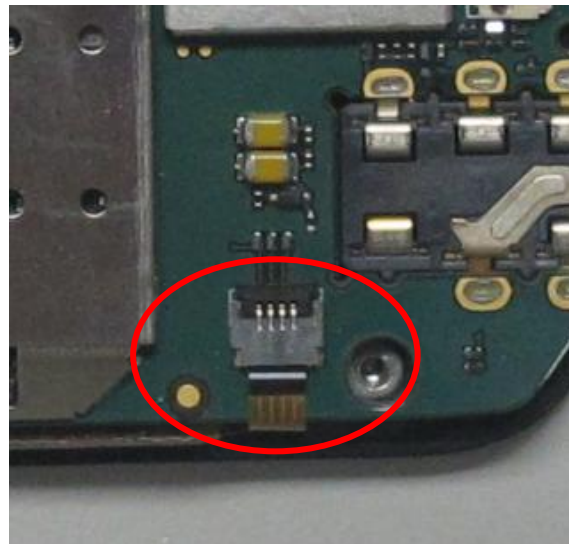
7) 用塑料镊子+无尘布慢慢顶起摄像头镜片，然后取下镜片



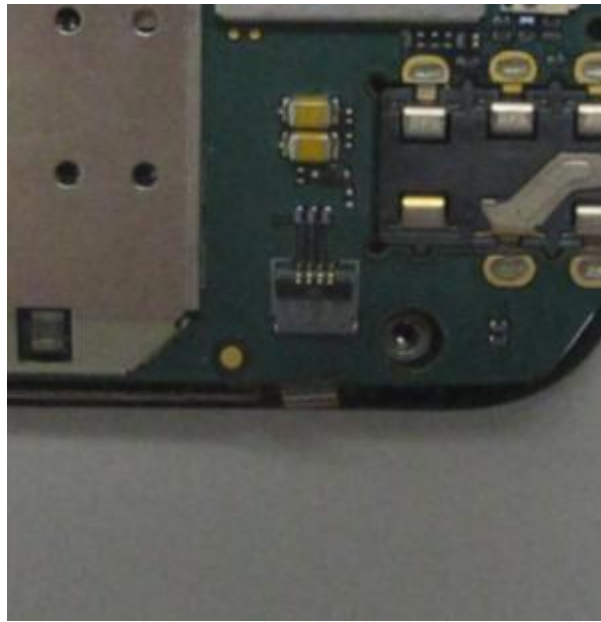
9) 打开触摸屏 FPC 接口压片



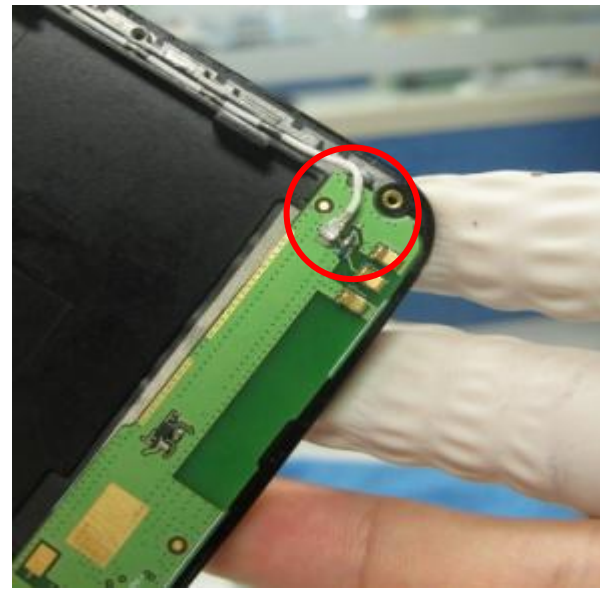
10) 取出触摸屏 FPC。



11) 打开音量键 FPC 接口压片



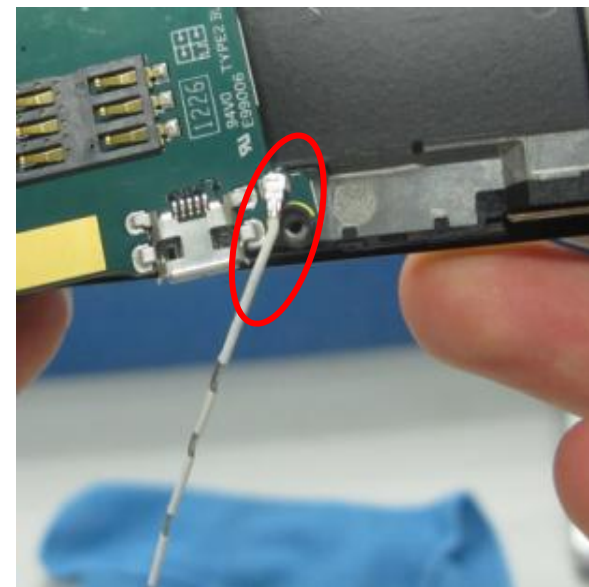
12) 从接口内取出音量键 FPC



13.) 拆下 cable 线 (副板端)



14.) 取下主板 FPC (副板端)



15.) 拆下 cable 线 (主板端)



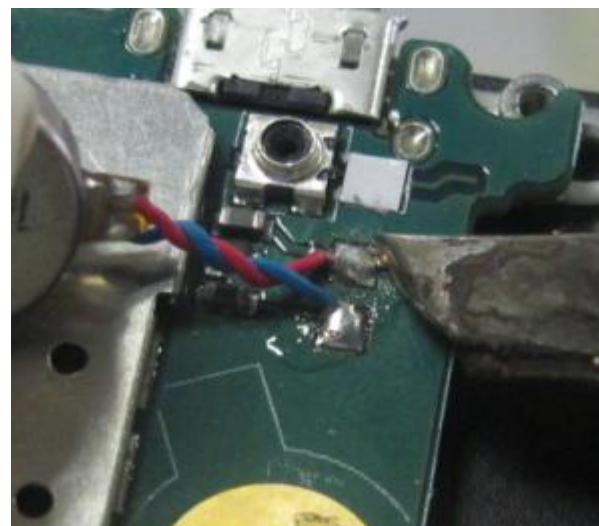
16.) 用镊子撕下主 fpc 连接器固定黑膜



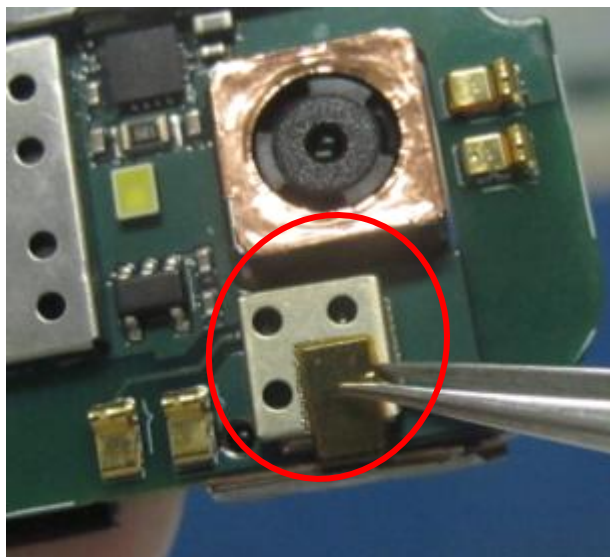
17.) 拆下主板 FPC (主板端)



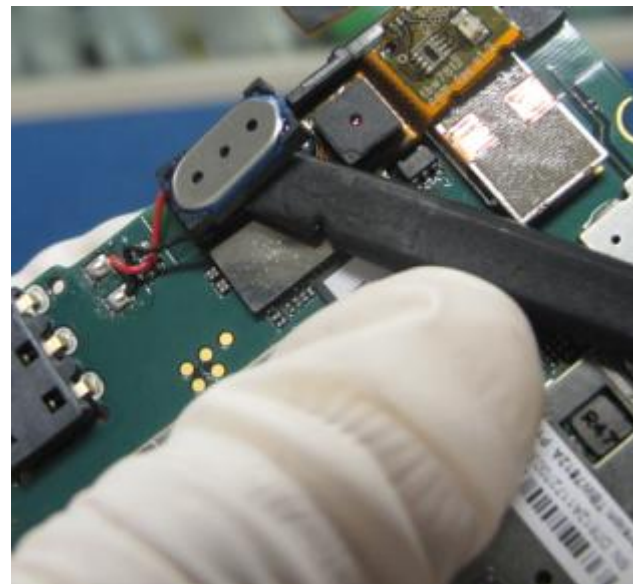
18.) 用手术刀撬起马达



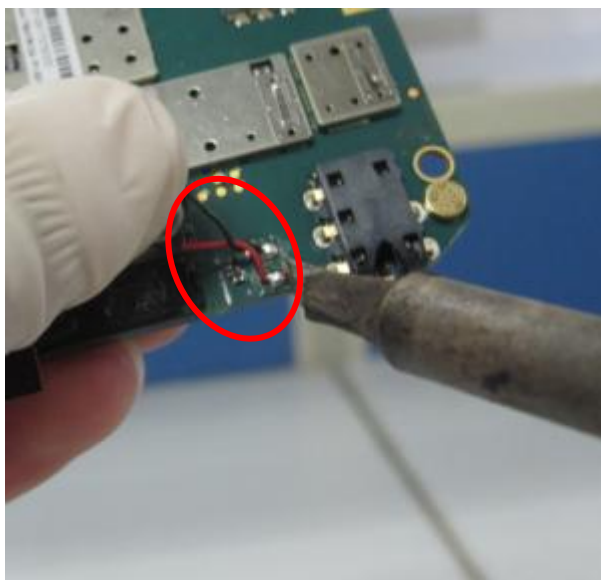
19.) 焊下马达



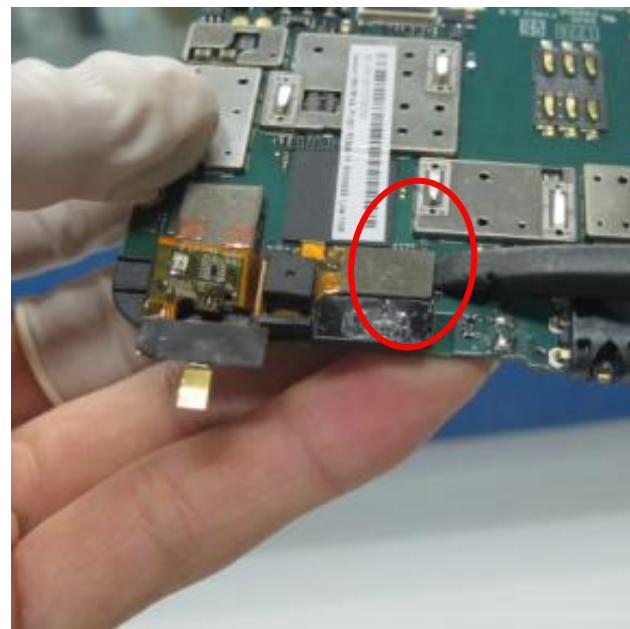
20.) 用镊子拆下前置摄像头组件



23.) 用塑料镊子跷起受话器组件



24.) 焊下受话器组件



25.) 用塑料镊子拆下前摄像头组件



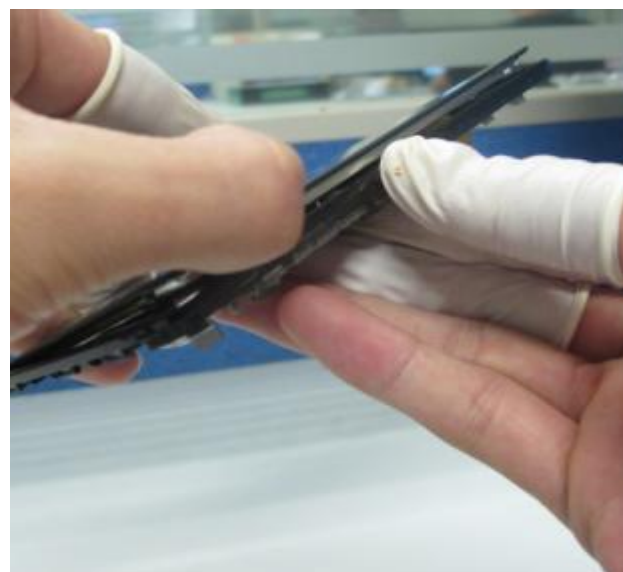
26.) 取下摄像头



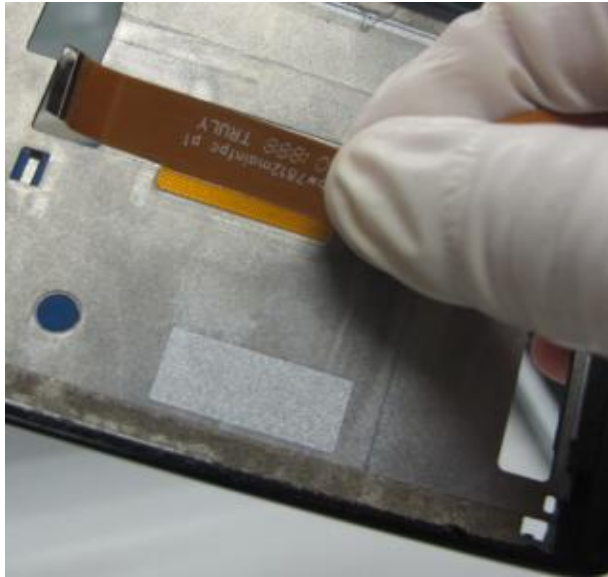
26) 前壳组件与主板分开的效果图



27.) 取下临近感应器避光罩, (注意装机务必装回否则打电话黑屏



28) 拆卸显示屏前后需预热, 时间需要二分钟, 温度 120°C



29) 撕下主 FPC



30) 拆下前壳音量键组件



31) 显示屏与前壳分开的效果图



32.) 全家福

特殊物料识别



名称：显示屏

描述：LCD+电容屏组件为一体，不可分离

料号：TYC045TL009179T



名称：前壳组件

料号：TYC7812A010008



名称：后壳组件

描述：后壳组件包括 WIFI 天线、GPS 天线、主天线

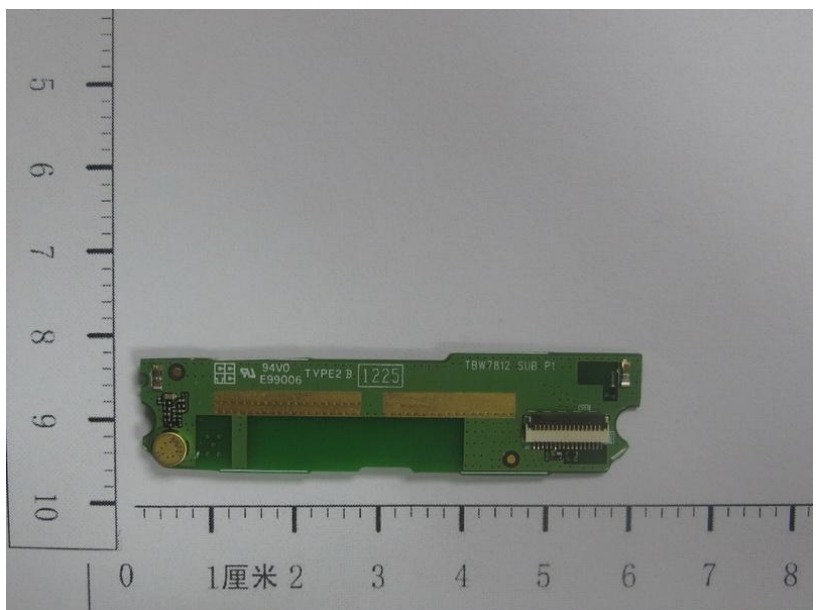
料号：TYC7812A020008



名称：电池盖

描述：电池盖包含电源键、音量键

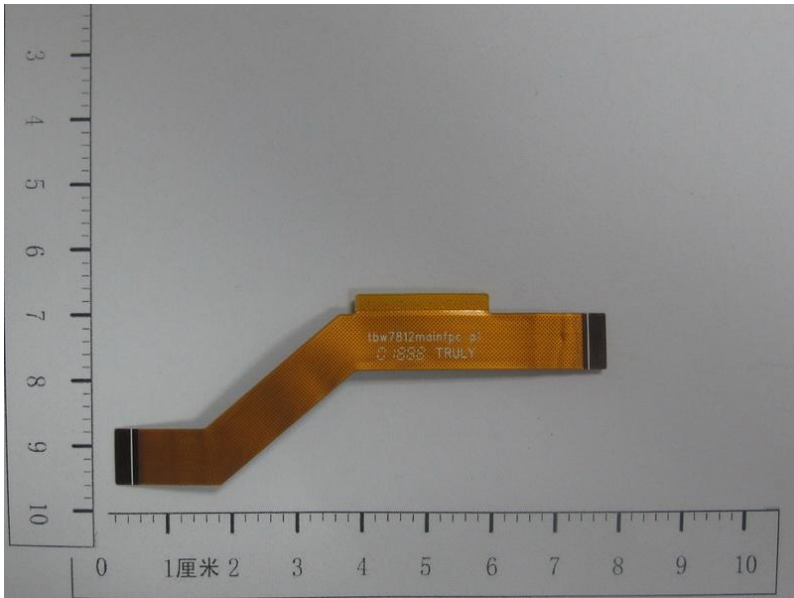
料号：TYC7812A050308



名称：副板

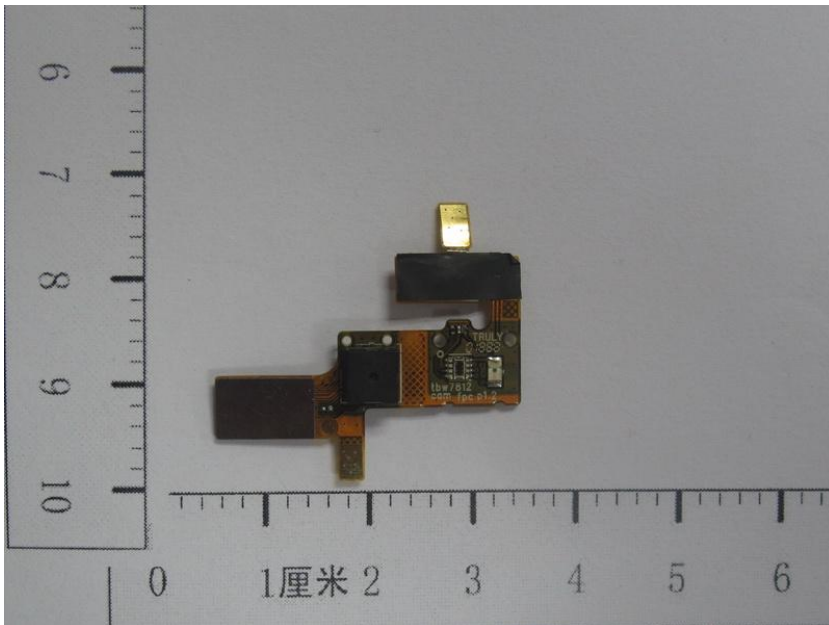
描述：副板包含 MIC 组件

料号：TYC781280410110



名称：主 FPC

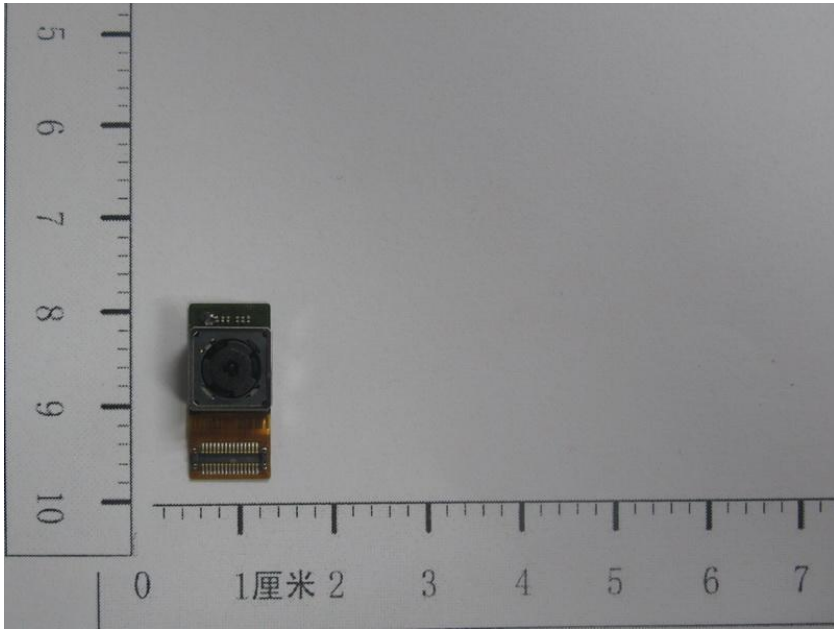
料号：TY0220126T



名称：前摄像头组件

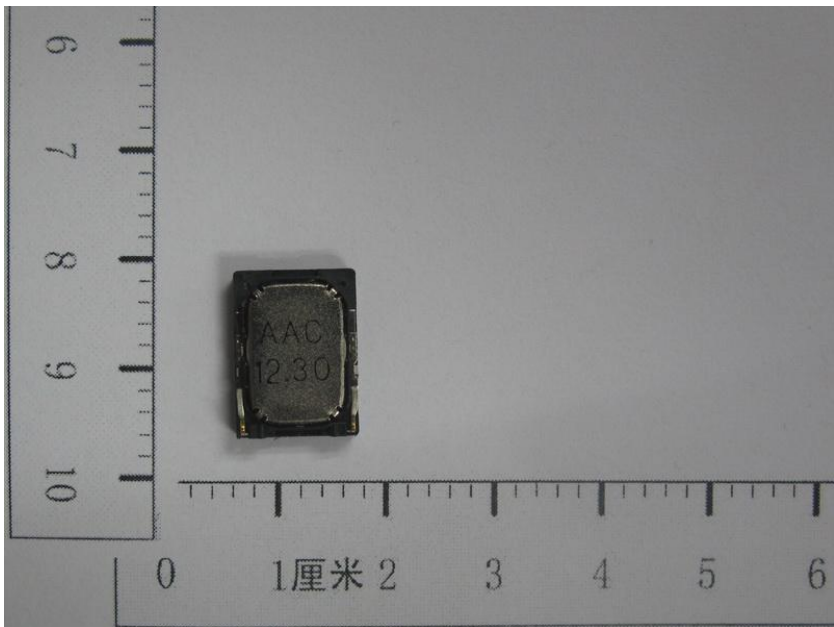
描述：前摄像头组件包含临近传感器、光线传感器、前摄像头

料号：TYC781280420511



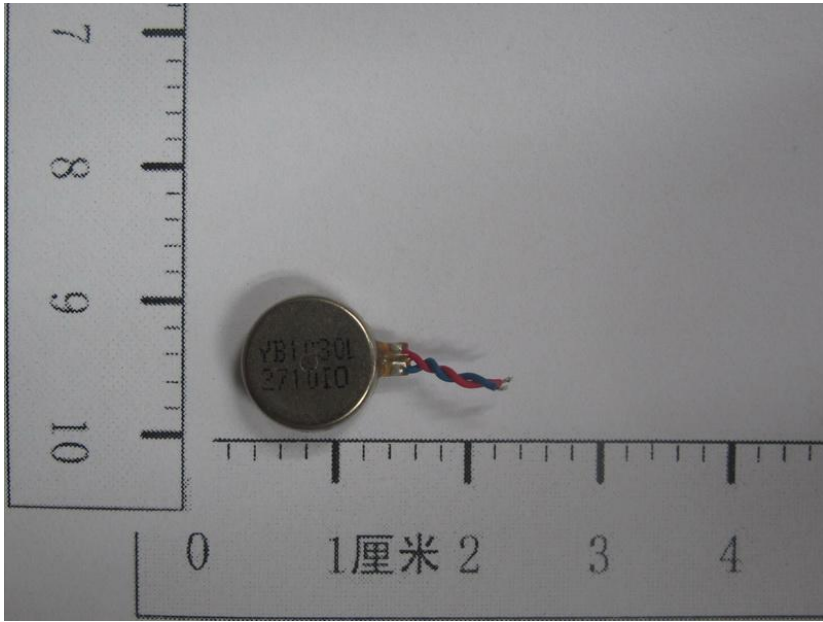
名称：后摄像头

料号：TYC500BA11189S



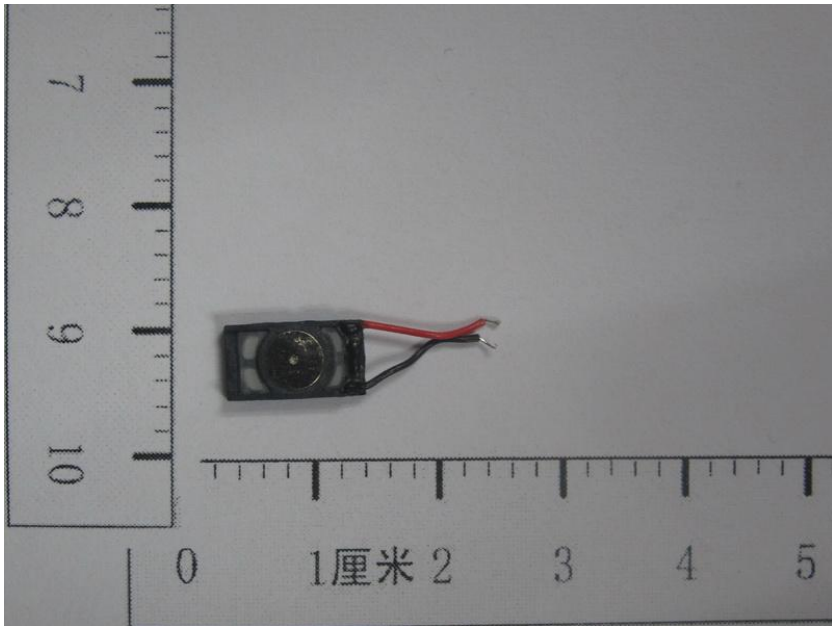
名称：扬声器

料号：TYC7802A1200K8



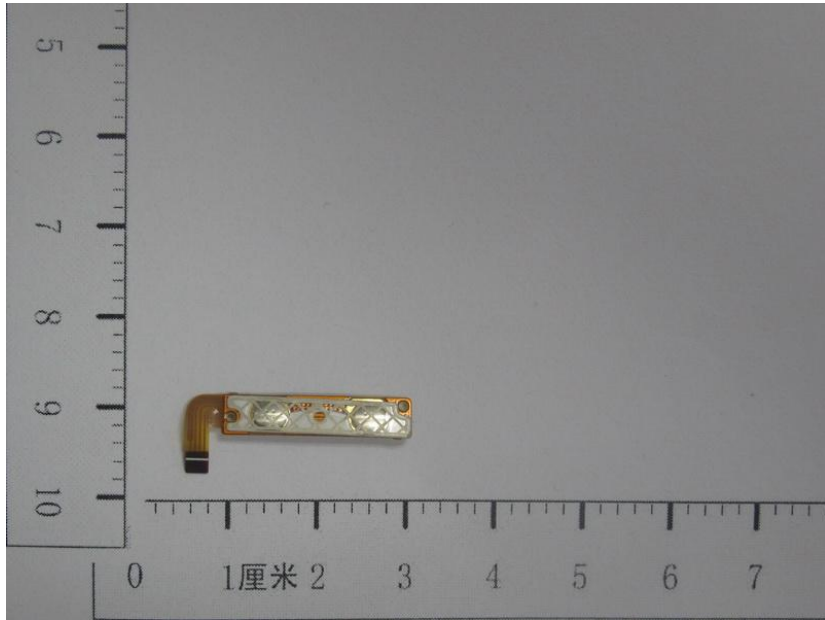
名称：马达

料号：TYC2217A1500



名称：受话器

料号：TYC5913B1300K8



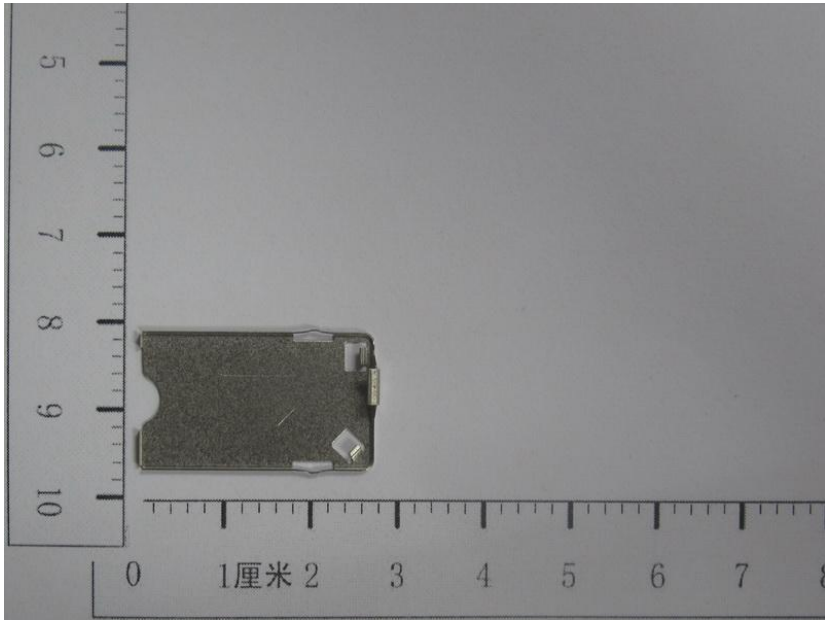
名称：音量键 FPC 组件

料号：TYC7812A1800T



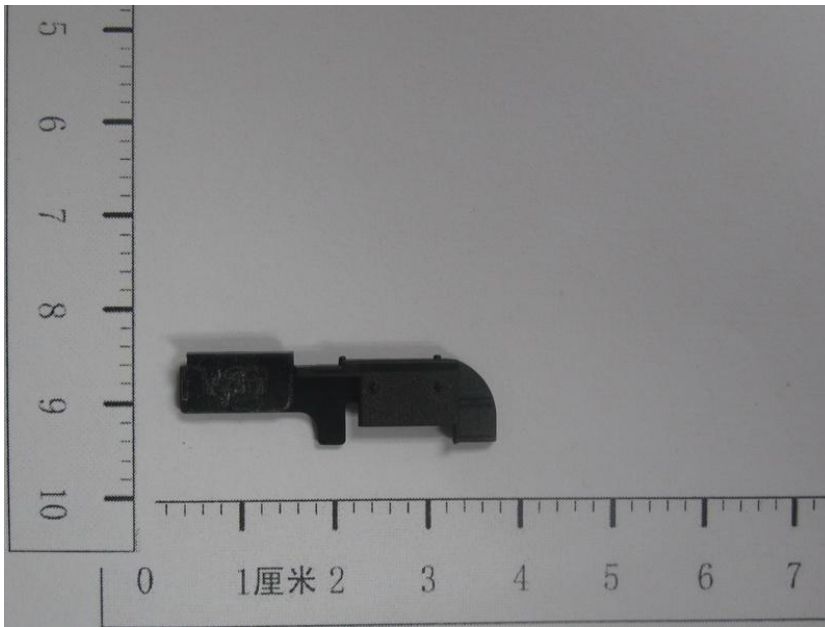
名称：cable 线

料号：TYC7812A200056



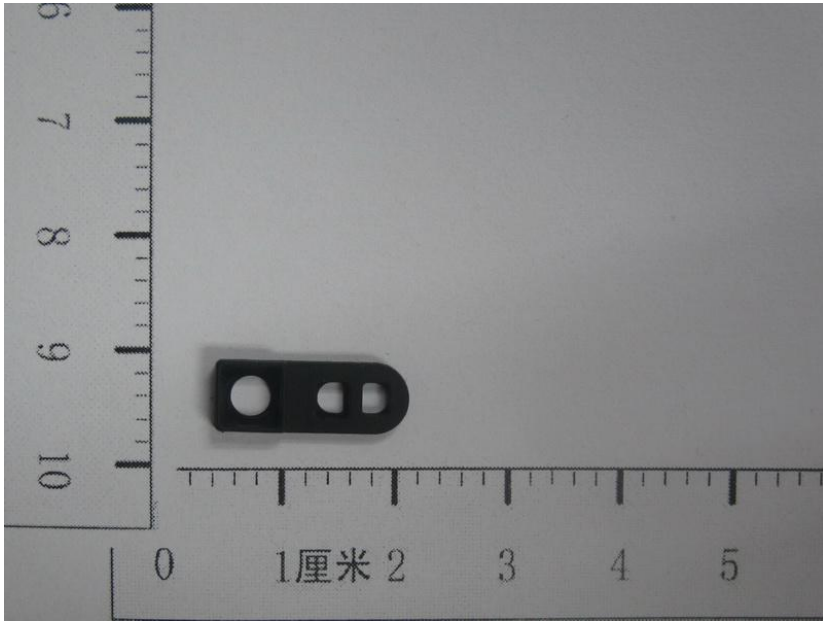
名称: sim 卡托盘

料号: TYC7812A2800P2



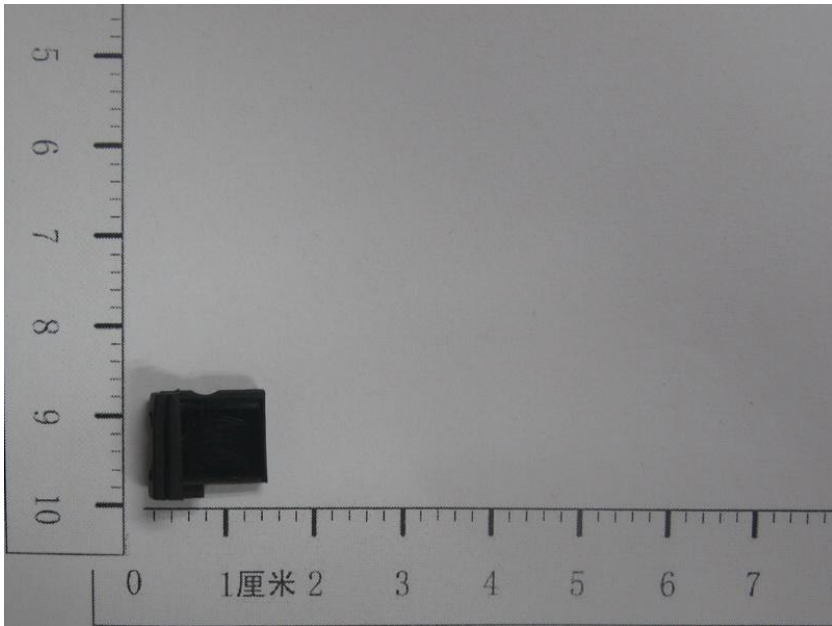
名称: 前摄像头支架组件

料号: TYC7812A280108



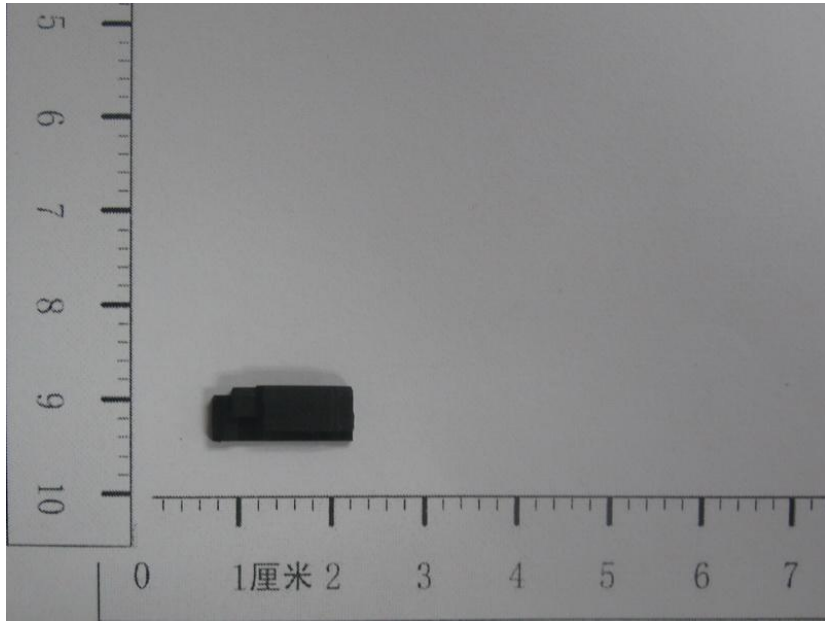
名称：距离传感器硅胶套

料号：TYC7812A230250



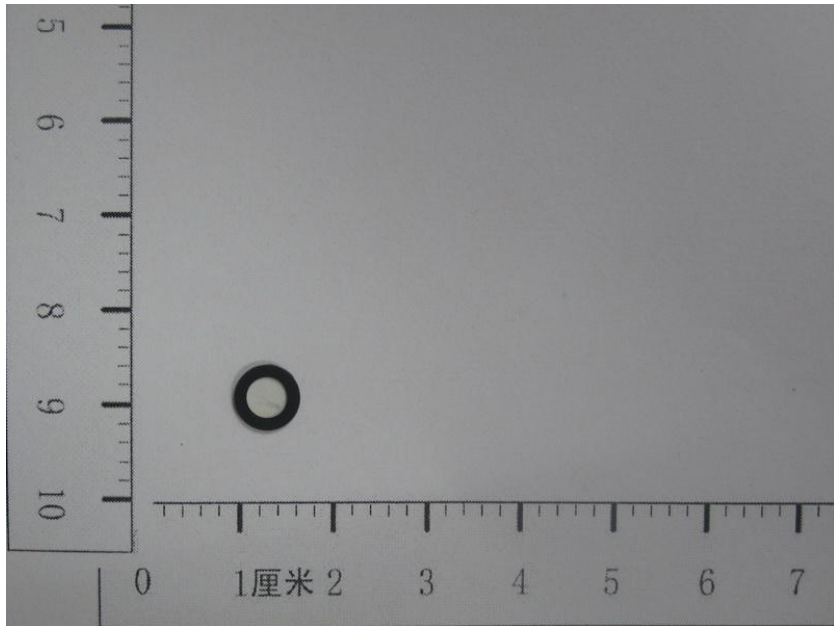
名称：耳机座硅胶套

料号：TYC7812A230050



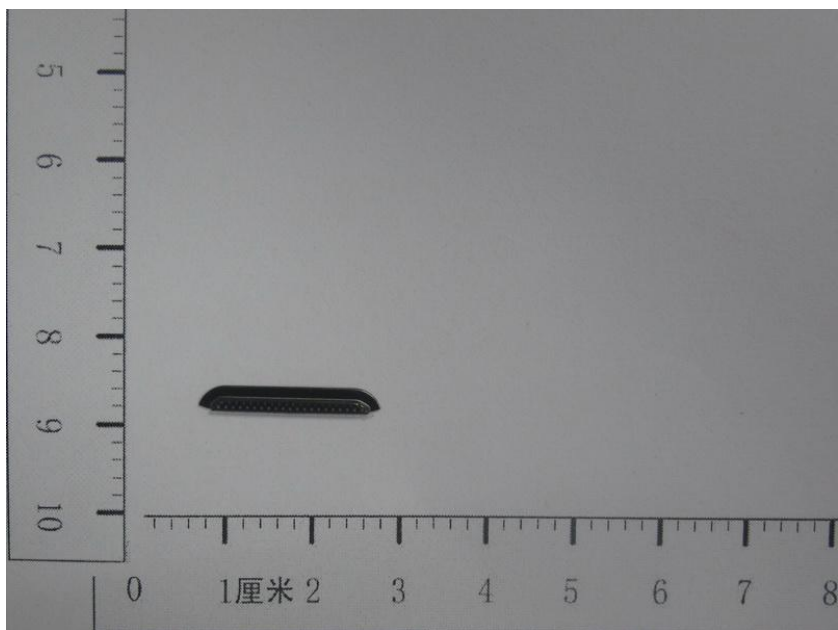
名称：usb 硅胶套

料号：TYC7812A230150



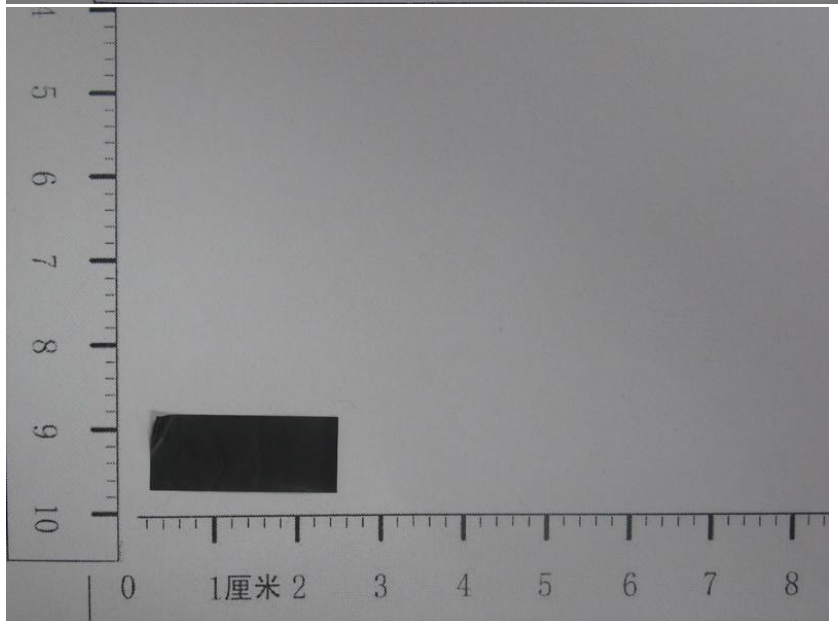
名称：后摄像头镜片

料号：TYC7808A070421



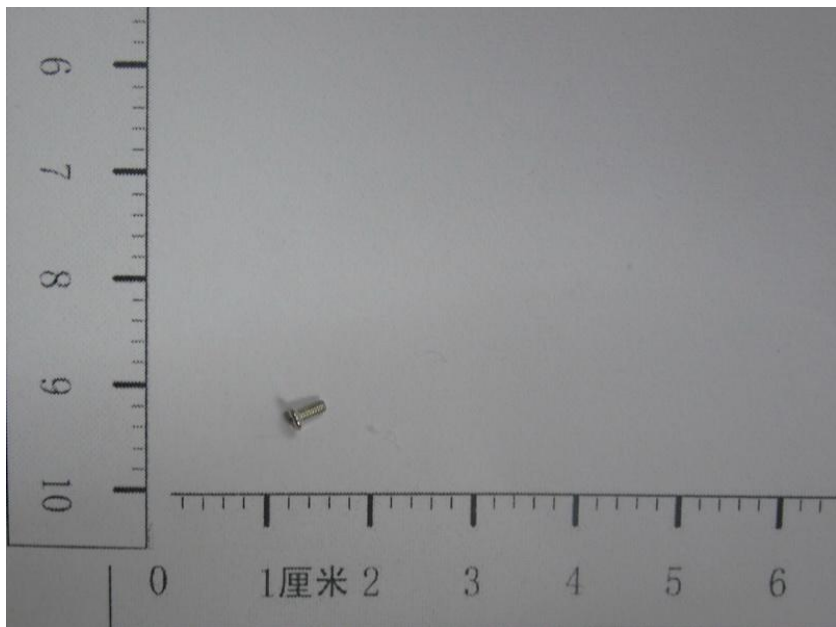
名称：听筒装饰件组件

料号：TYC7812A070184



名称：lcd 器件保护黑膜

料号：TYC7812A222036



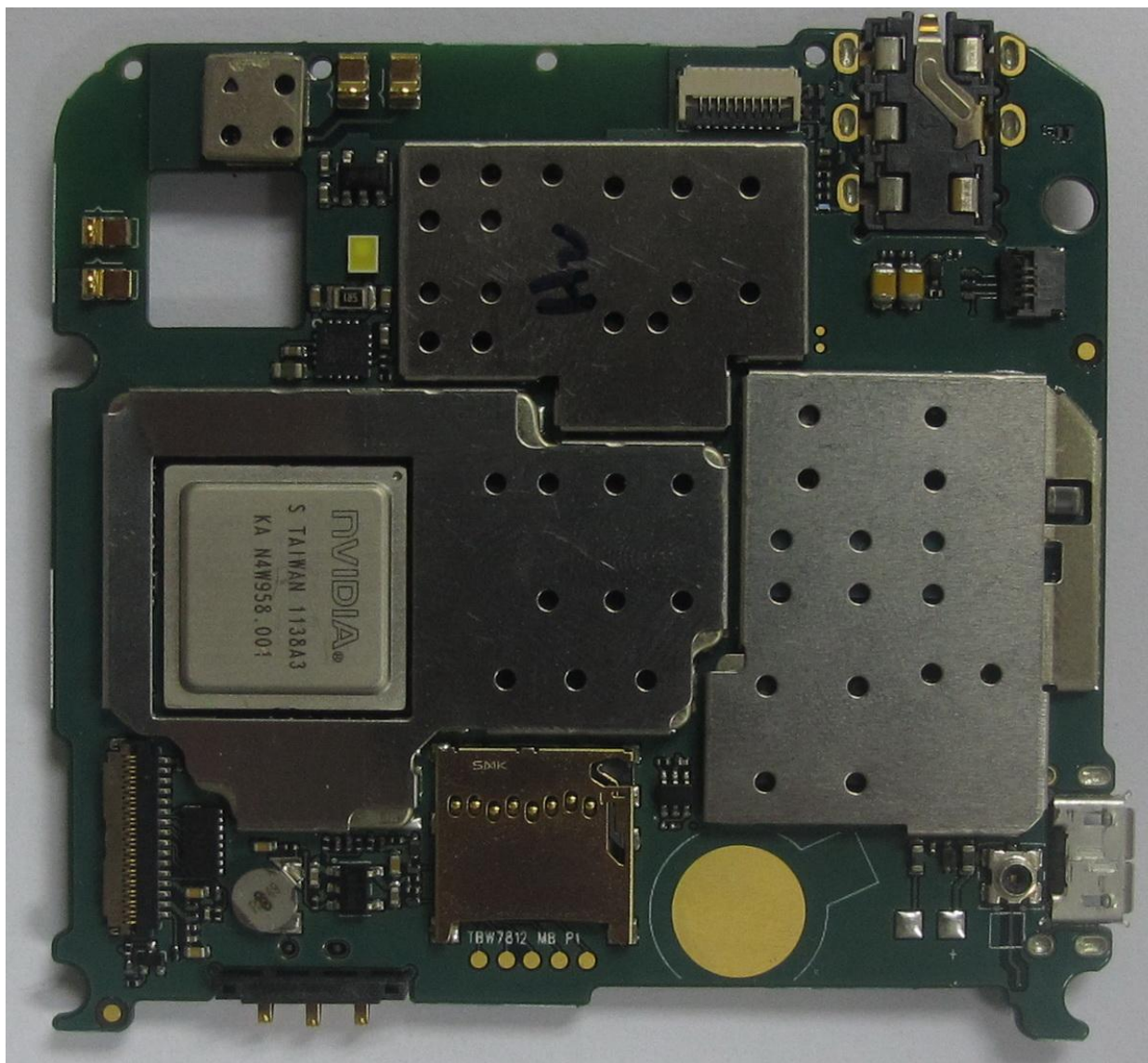
名称：螺钉

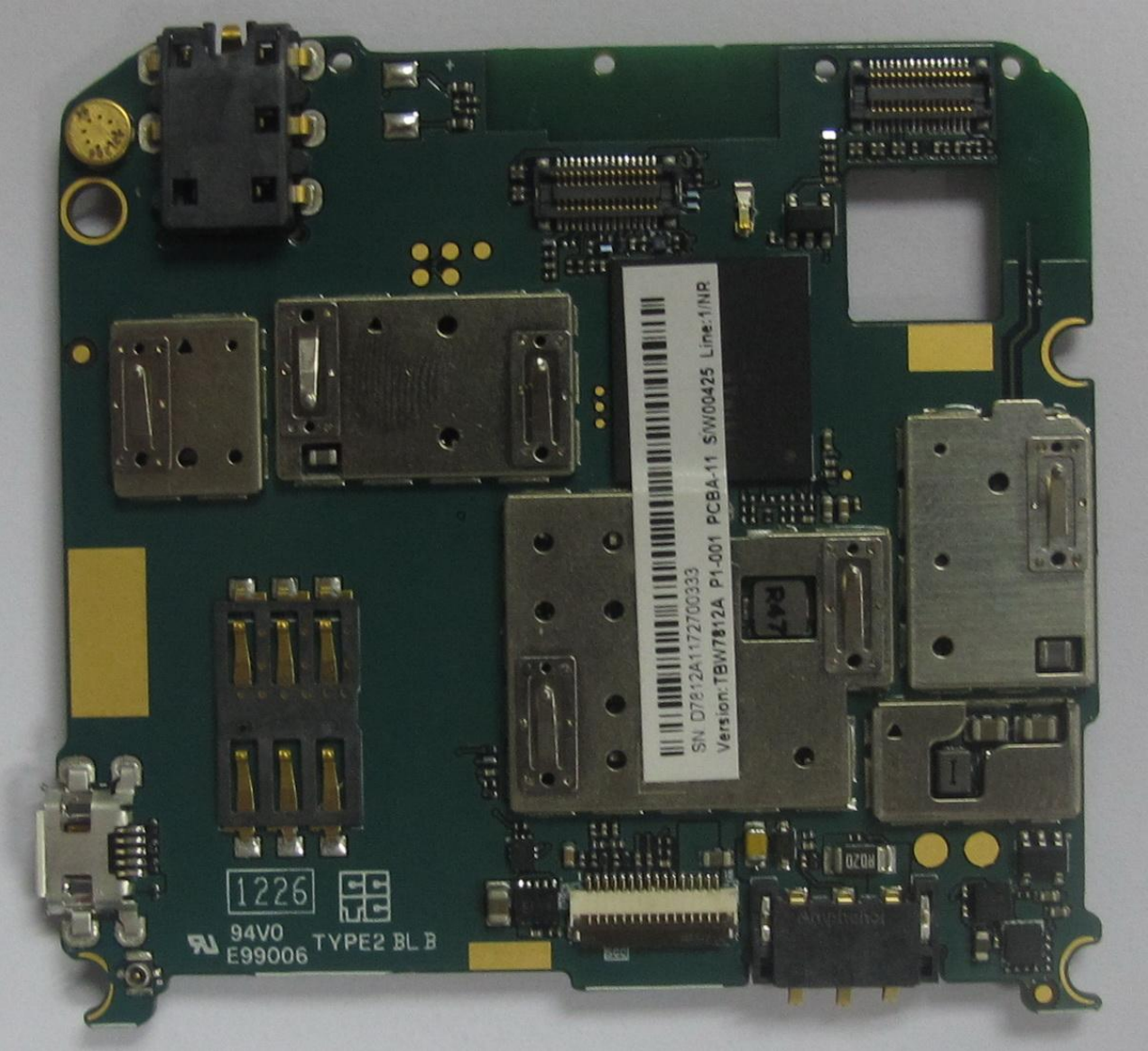
描述：M1.4*3.0*2.5*0.5

料号：TYC620A1900

主板外观图

TBW7812 MB P1

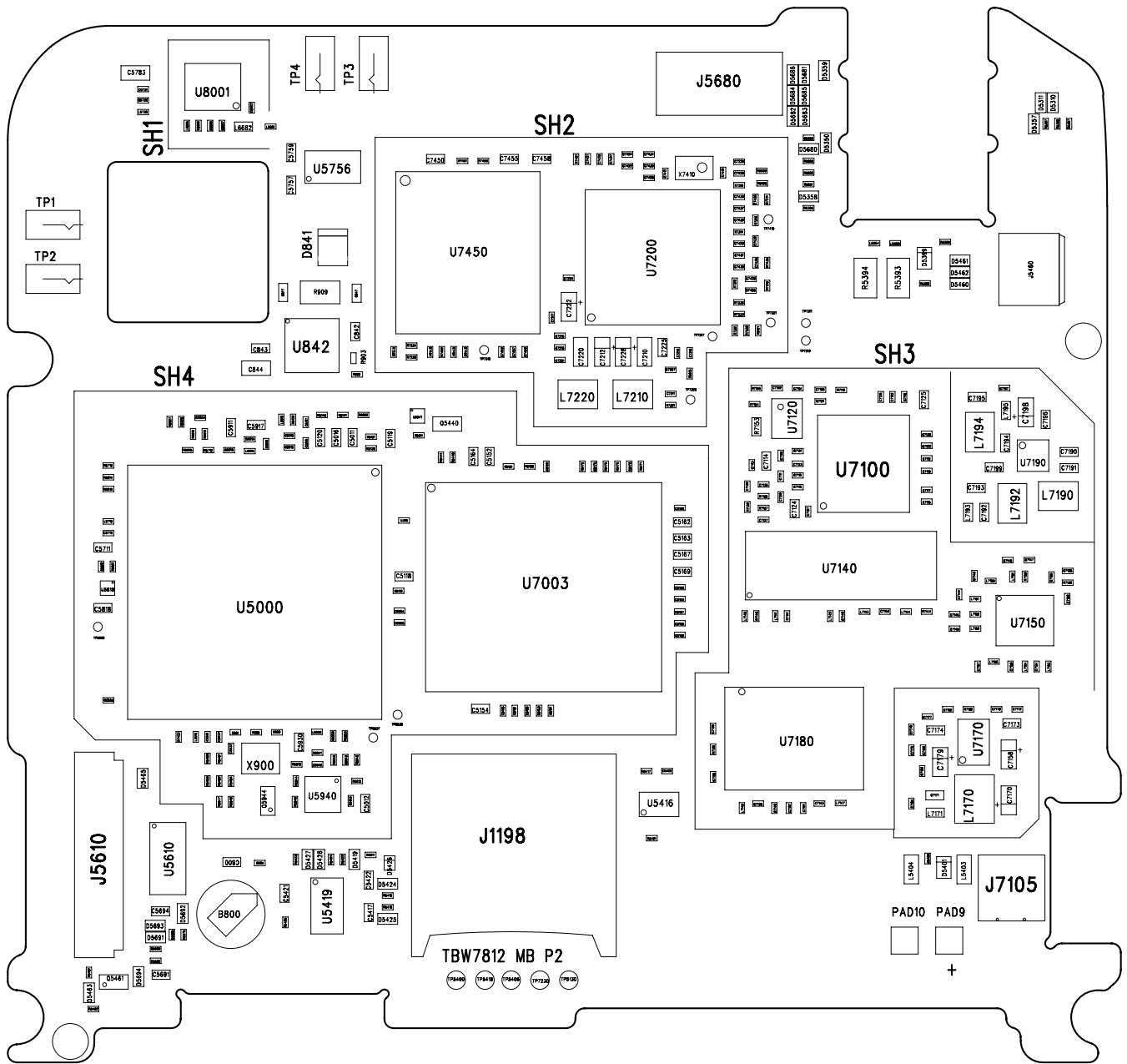


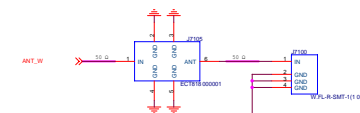
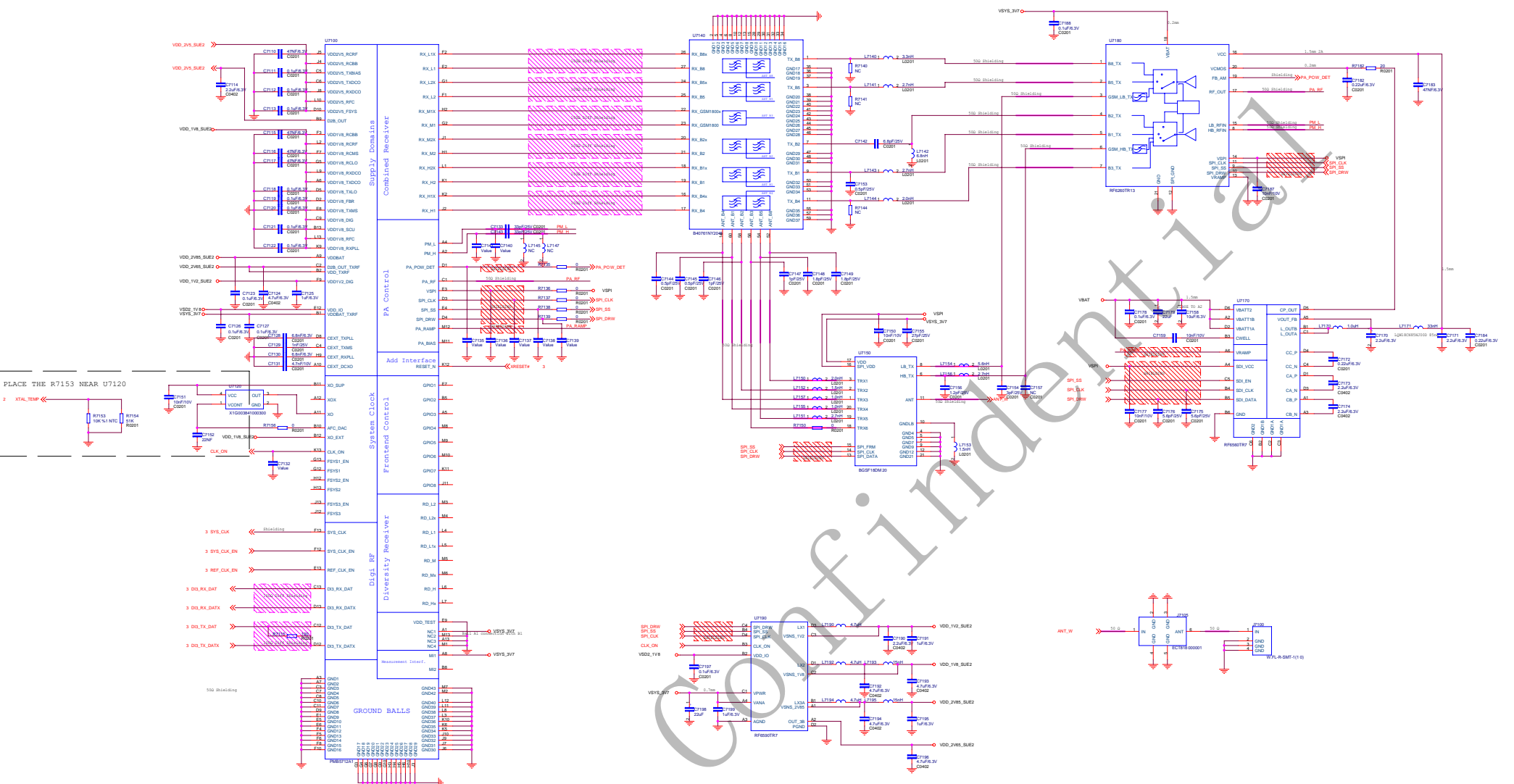


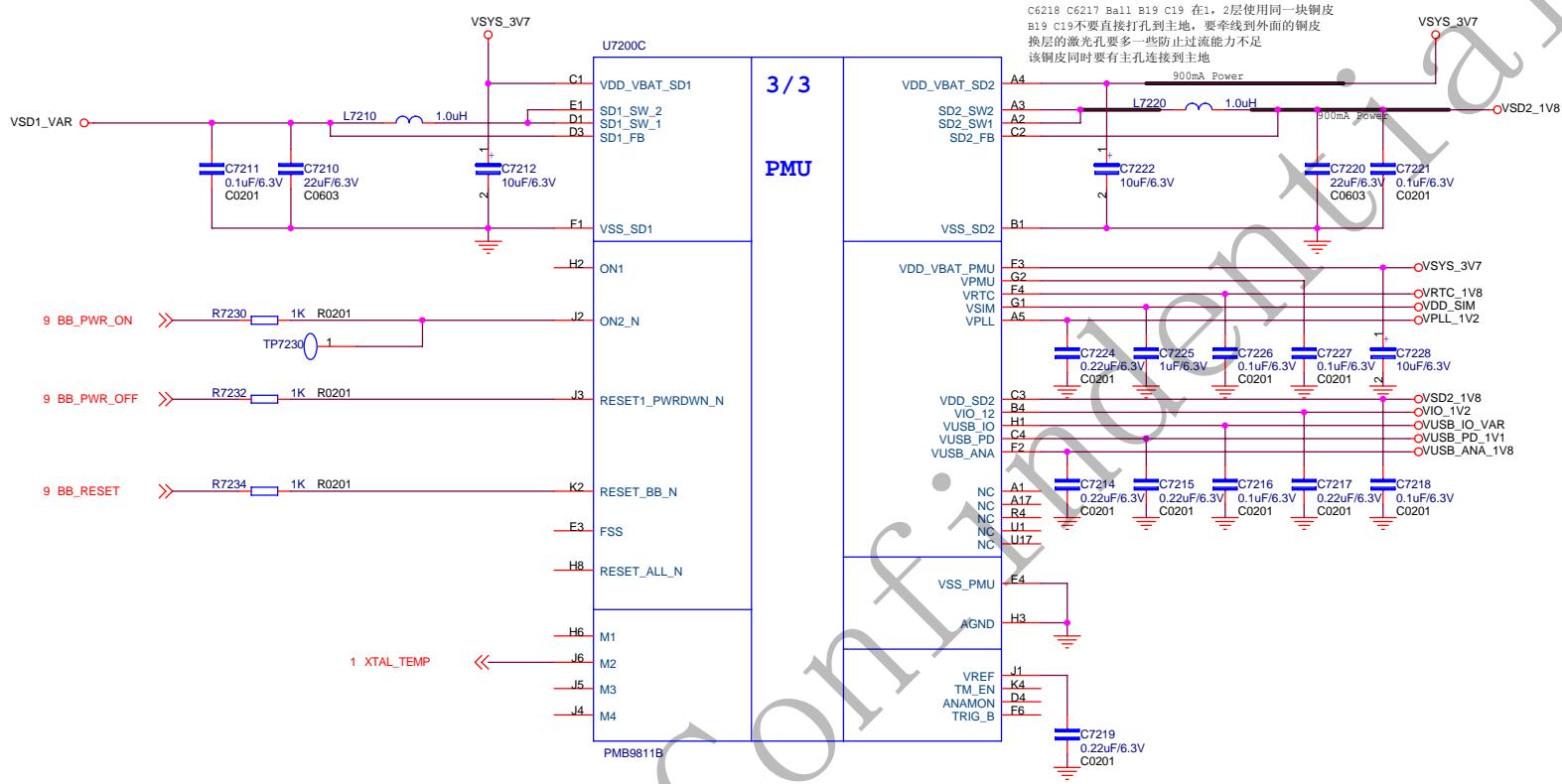
SN: D7812A117ZT00333
Version: TBW7812A P1-001 PCBA-11 SW00425 Line: 1/NR

1226

94V0 TYPE2 BL B
E99006







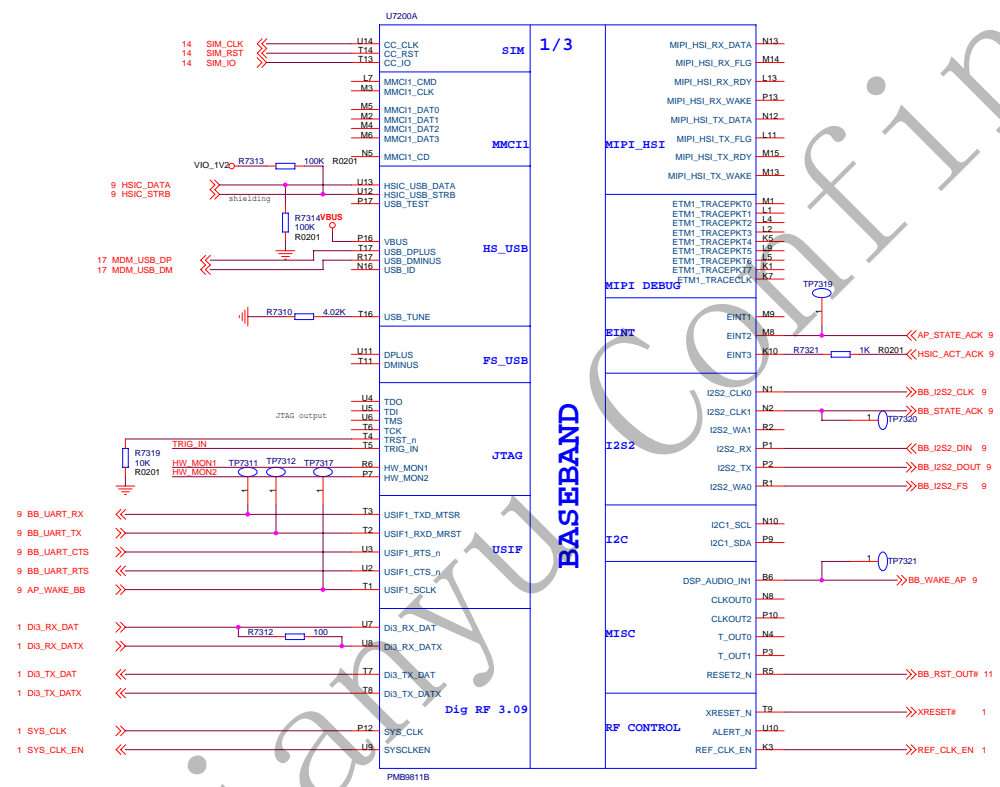
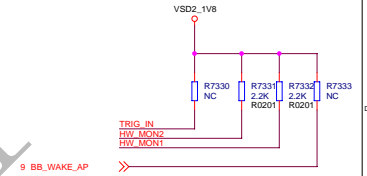
POWER_NET	VOLTAGE
VSD_1	0.9V-1.8V(20mV steps)
VSD_1V8	1.8V
VANA1	1.3V
VANA2	2.5V
VPMU	1.3V
VRTC	2.3V
VMIFI	1.2V
VPLL	1.35V
VRF1	2.85V
VRF2	2.85V
VSIM	1.8V/2.85V
VUSB	1.5V/2.85V/3.1V

C6218 C6217 Ball B19 C19 在1, 2层使用同一块铜皮
 B19 C19不要直接打孔到主地, 要牵线到外面的铜皮
 换层的激光孔要多一些防止过流能力不足
 该铜皮同时要有主孔连接到主地

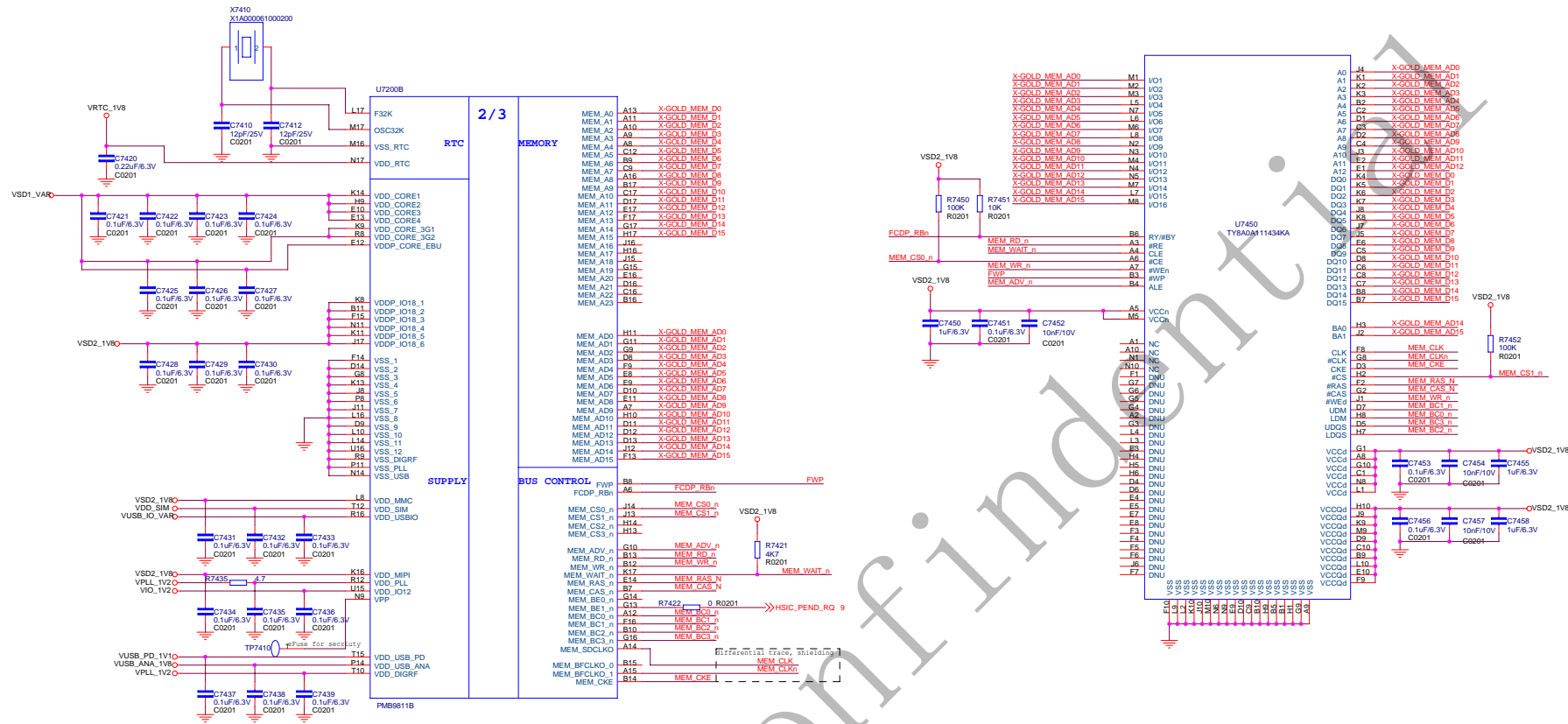
北京天宇朗通通信设备股份有限公司		
Title PMU		
Size A3	Document Number K-Touch V9	Rev
Date: Friday, August 10, 2012	Sheet 2	of 16

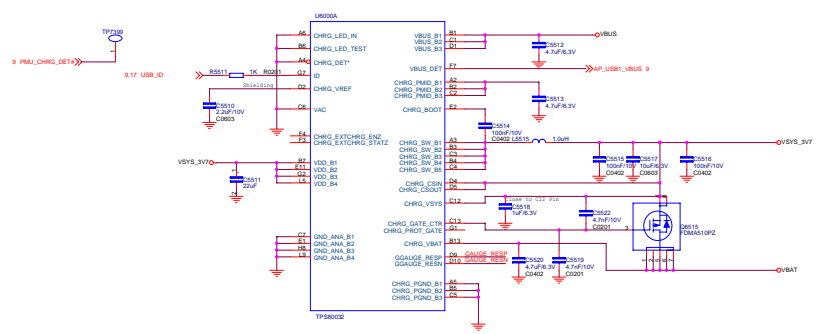
Boot Configuration
(only valid if no boot config eFuses are set!)

Boot Config	DSP_AUDIO_IN1 HWCFCG[3]	MON1 HWCFCG[2]	MON2 HWCFCG[1]	TRIG_IN HWCFCG[0]	Boot Config Description
1	0	0	0	1	16-bit AD muxed NOR Flash
2	0	0	1	0	16-bit AAD muxed NOR Flash
4	0	1	0	0	16-bit muxed DDR NOR Flash
5	0	1	0	1	8-bit NAND Flash
6	0	1	1	0	16-bit NAND Flash
7	0	1	1	1	16-bit muxed Data burst Flash
9	1	0	0	1	eMMC - connected to MMC12
12	1	1	0	0	16-bit muxed (DDR) SDRAM
14	1	1	1	0	Flashless boot
15	1	1	1	1	External boot directly from Flash via EBU (no ARM11 Boot ROM involved)

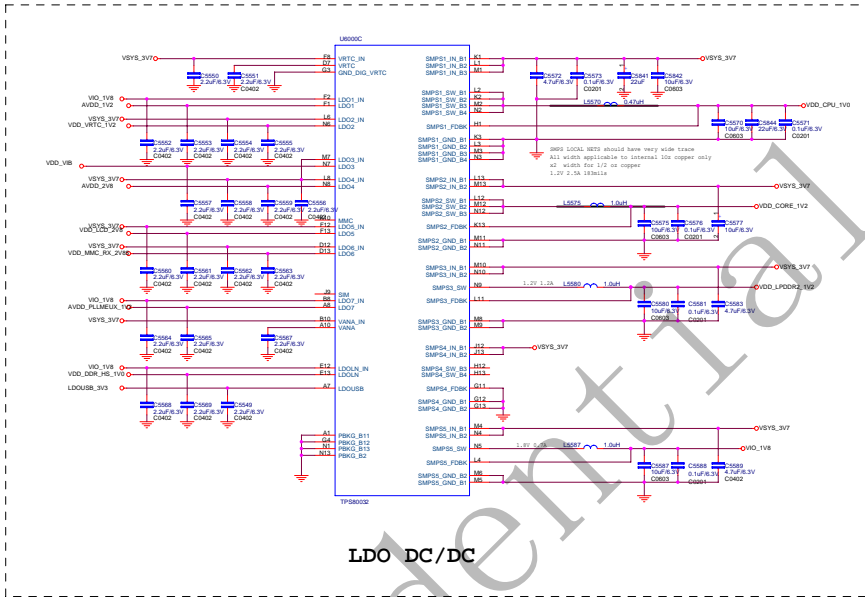


Confidential

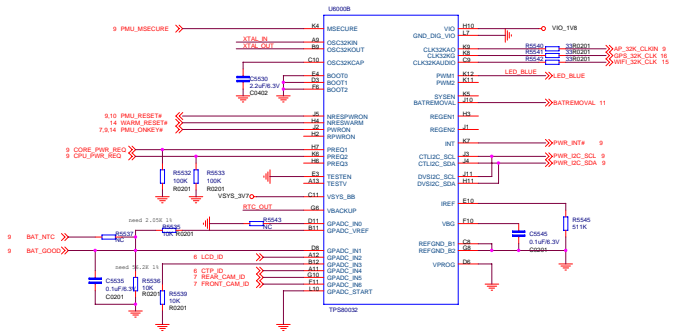




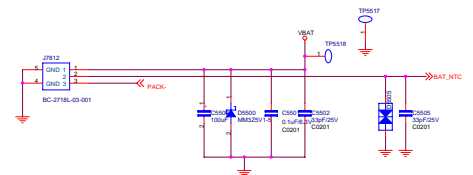
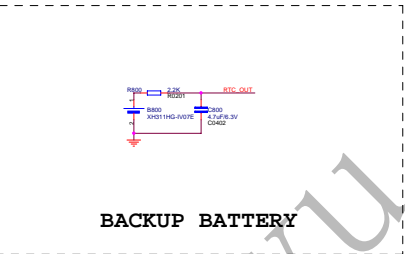
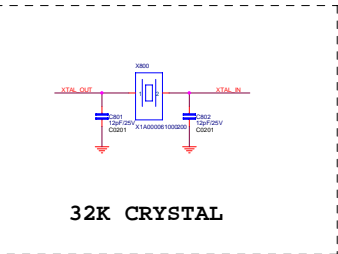
CHARGING



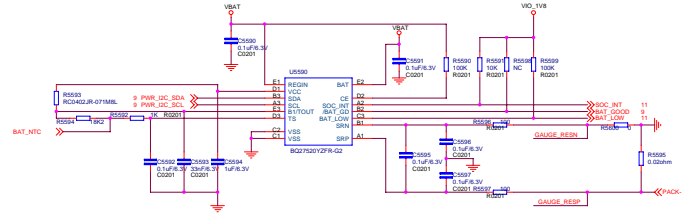
LDO DC/DC



CONTROL

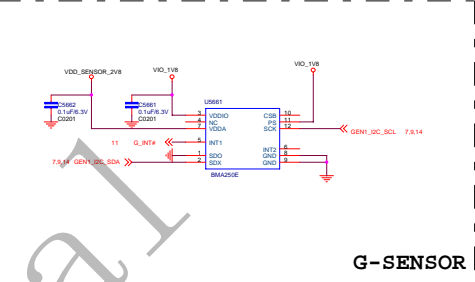
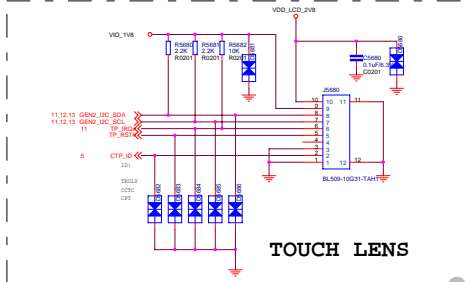
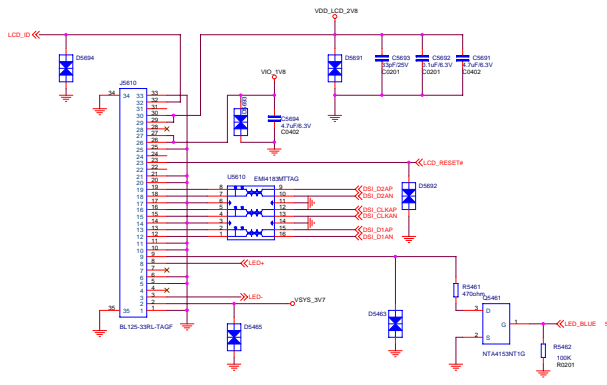


BATTERY CON



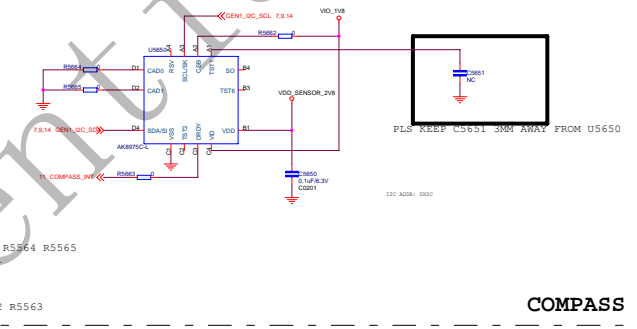
FUEL GAUGE

北京天守爾通信設備股份有限公司			
Doc ID	AP30 PMU		Rev
Doc Name	K-Touch V9		
Doc Date	Filed: August 13, 2014	Page	3 of 16

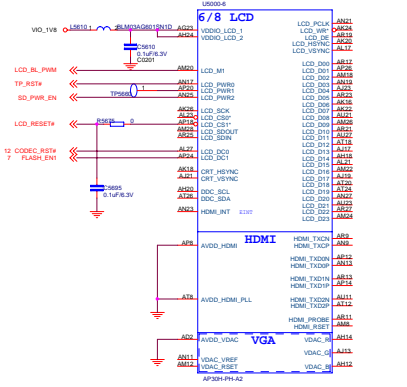


TOUCH LENS

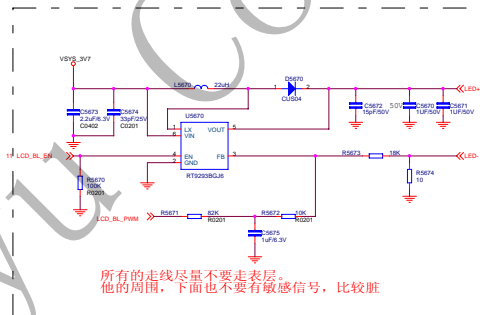
G-SENSOR



COMPASS



AP30 LCD INTERFACE



SENSOR POWER

所有的走线尽量不要走表层。
他的周围，下面也不要放敏感信号，比较脏

AK8975C:
MOUNT R5662 R5663 R5564 R5565
DO NOT MOUNT C5651

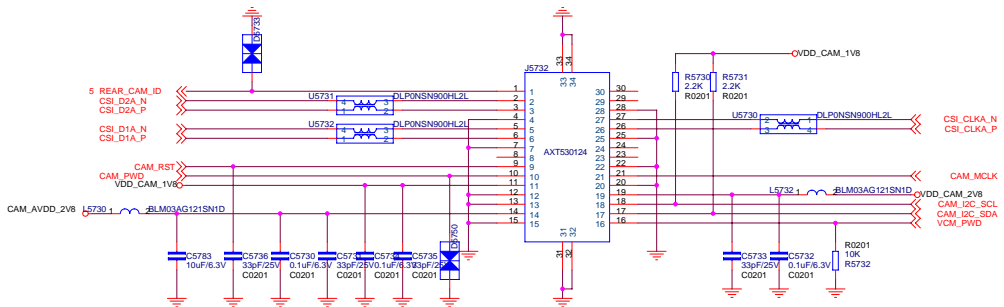
MXC3280:
MOUNT C5651
DO NOT MOUNT R5662 R5563
R5564 R5565

135 AD501-9303

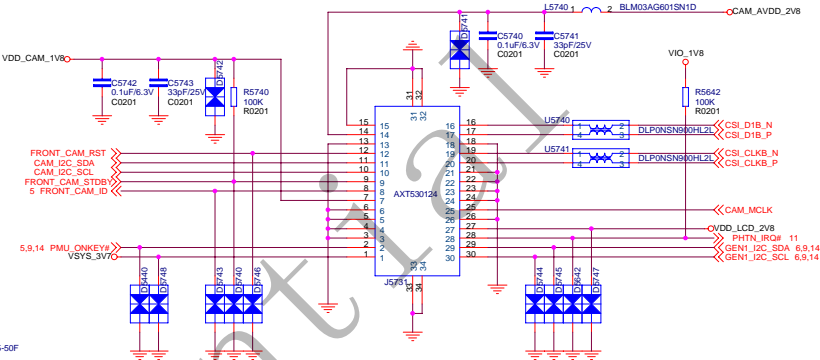
PL5 KEEP C5651 5MM AWAY FROM U5650



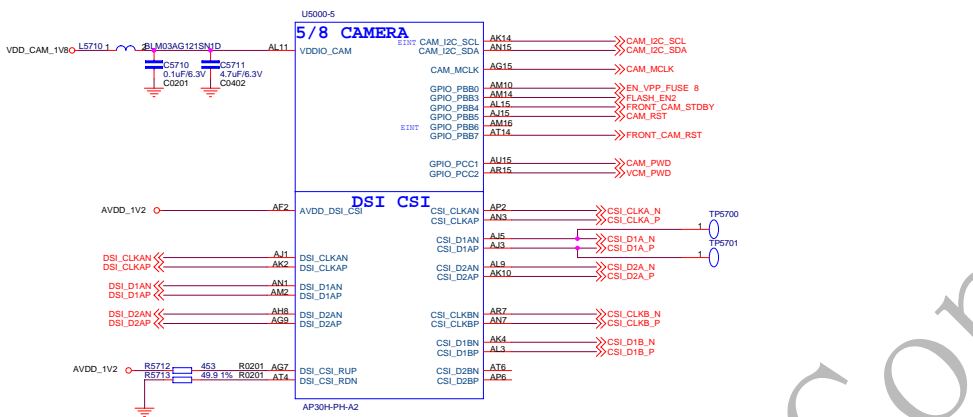
北京天宇润通通信设备有限公司			
Doc ID	AP30 LCD and Sensors		Ver
Doc No	K-Touch V9		
Doc Rev	Final, August 18, 2014		Page 5 of 16



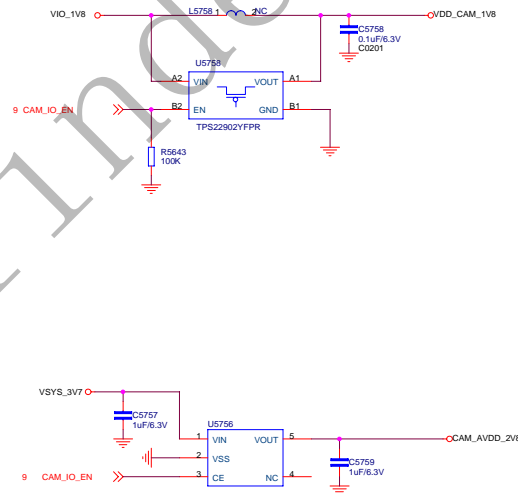
5M CAMERA (5647)



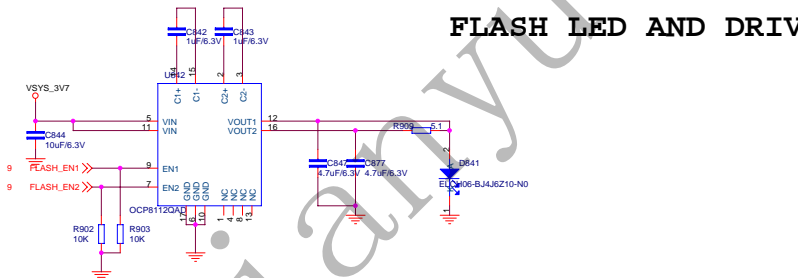
0.3M FRONT CAMERA



AP30 CAMERA INTERFACE



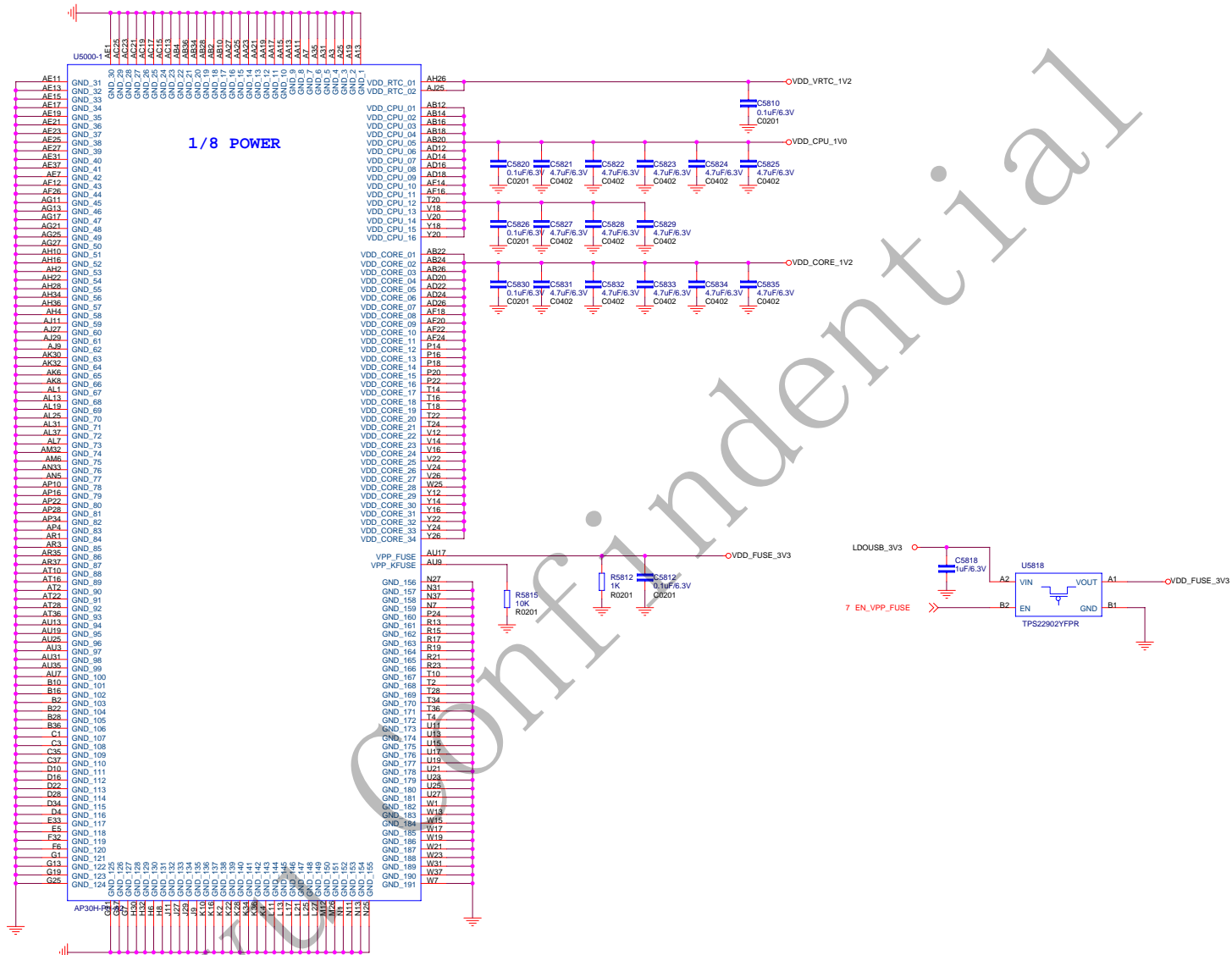
FLASH LED AND DRIVER



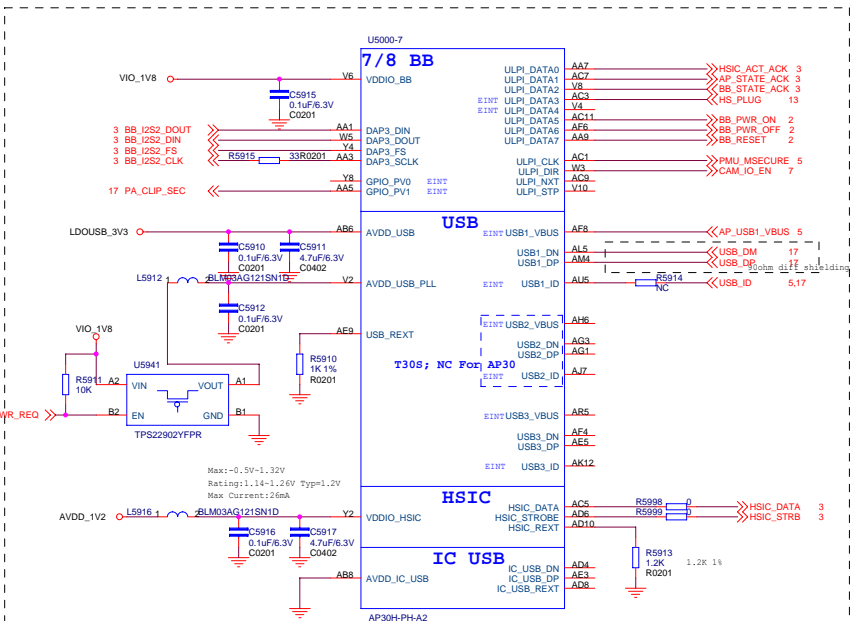
请注意，R908，R909和D841的两个PAD都尽量走表层，线要宽；如果不能走表层，也要多打盲孔，导热。
C842，C843，C847，C877请都靠近芯片处摆放

Camera Power Rails

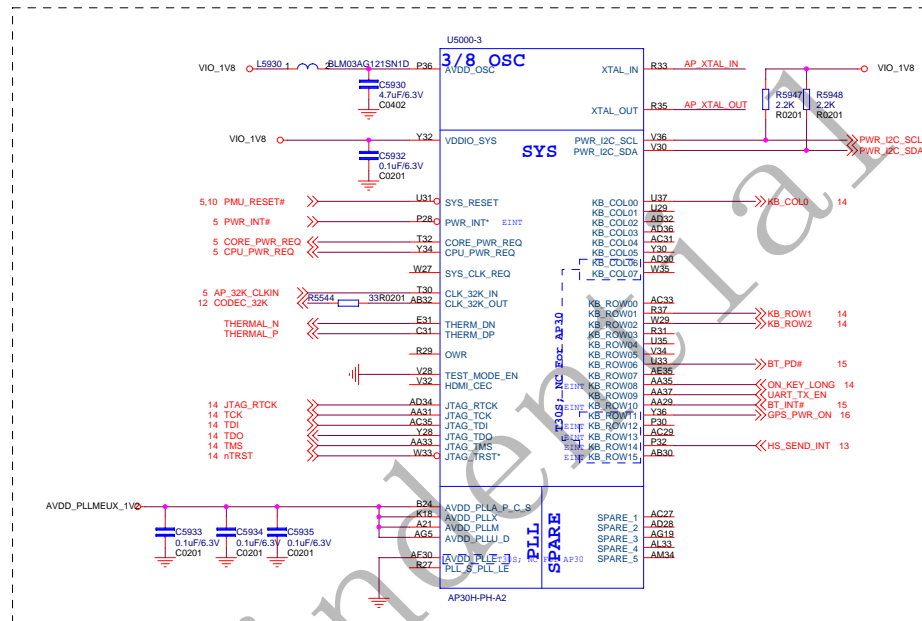
北京天宇朗通通信设备股份有限公司			
Title AP30 CAMERA			
Size	Document Number	Rev	
A2		K-Touch V9	
Date	Friday, August 10, 2012	Sheet	7 of 16



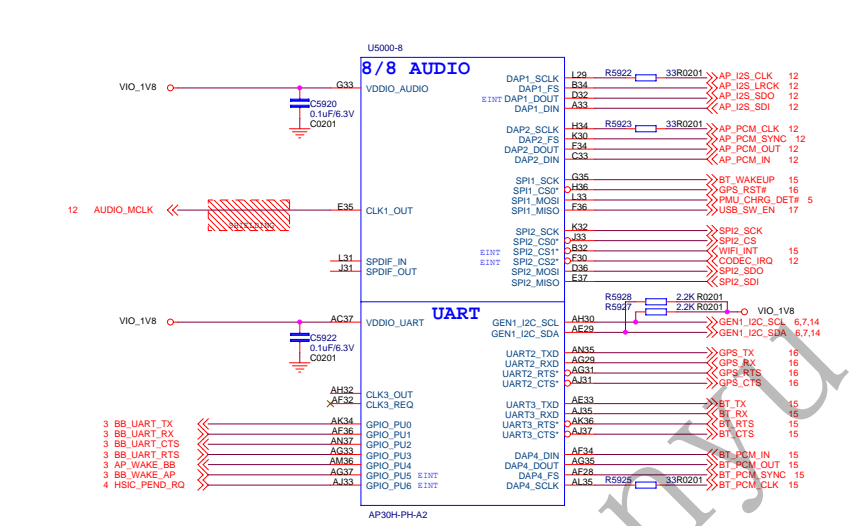
北京天宇朗通通信设备股份有限公司			
Title AP30 POWER			
Size C	Document Number	Rev	
Date: Friday, August 10, 2012		Sheet 8 of 16	



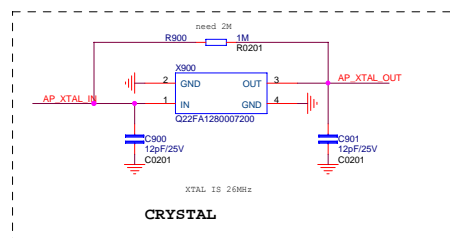
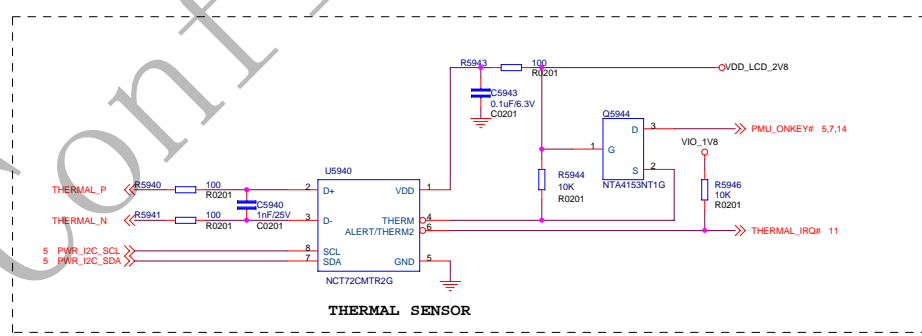
AP30 BB USB INTERFACE



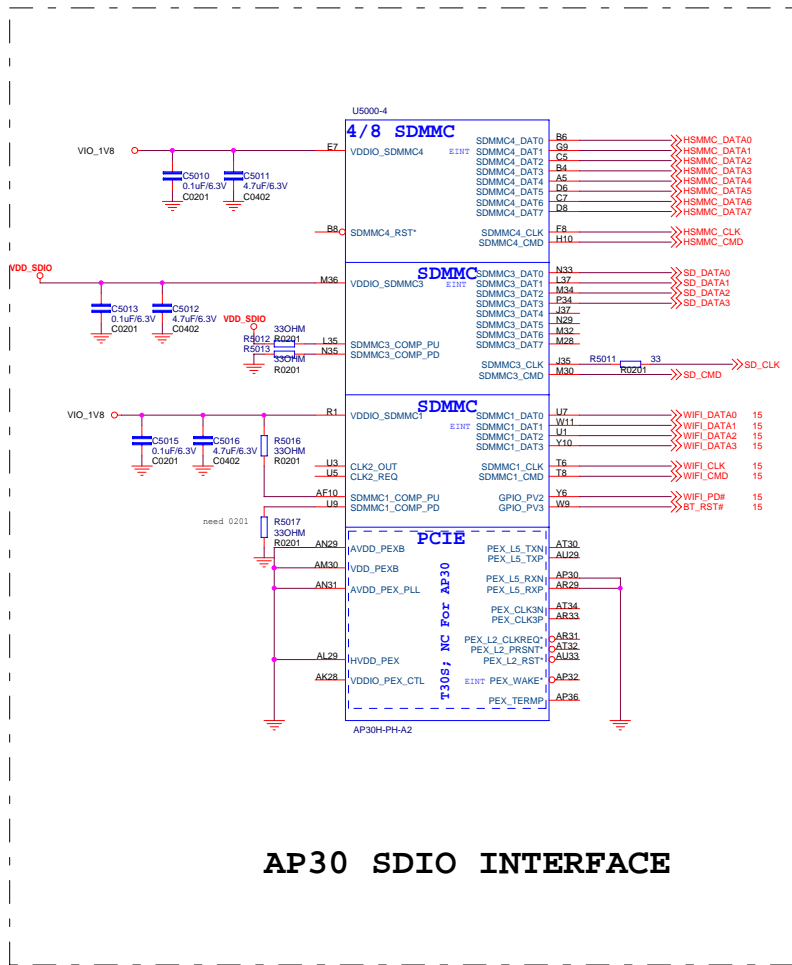
AP30 SYS INTERFACE



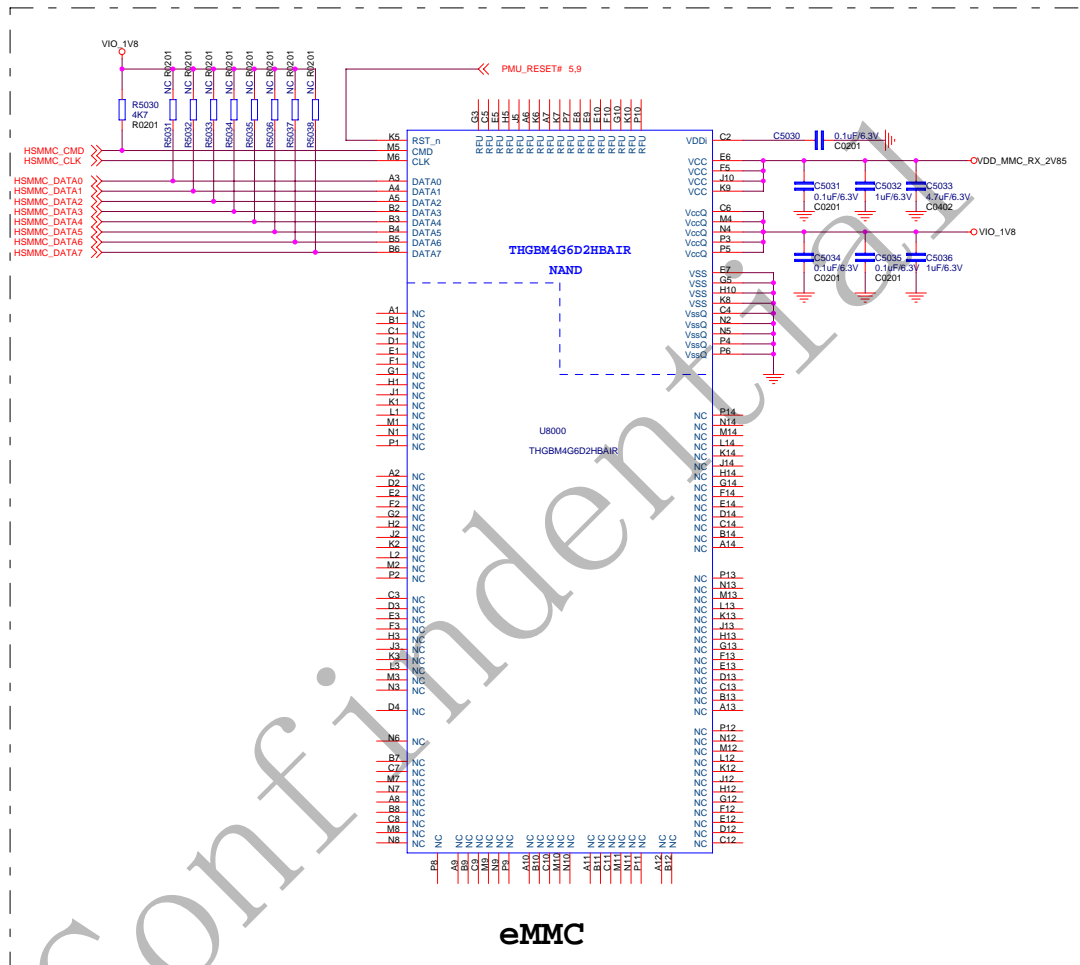
AP30 AUDIO UART INTERFACE



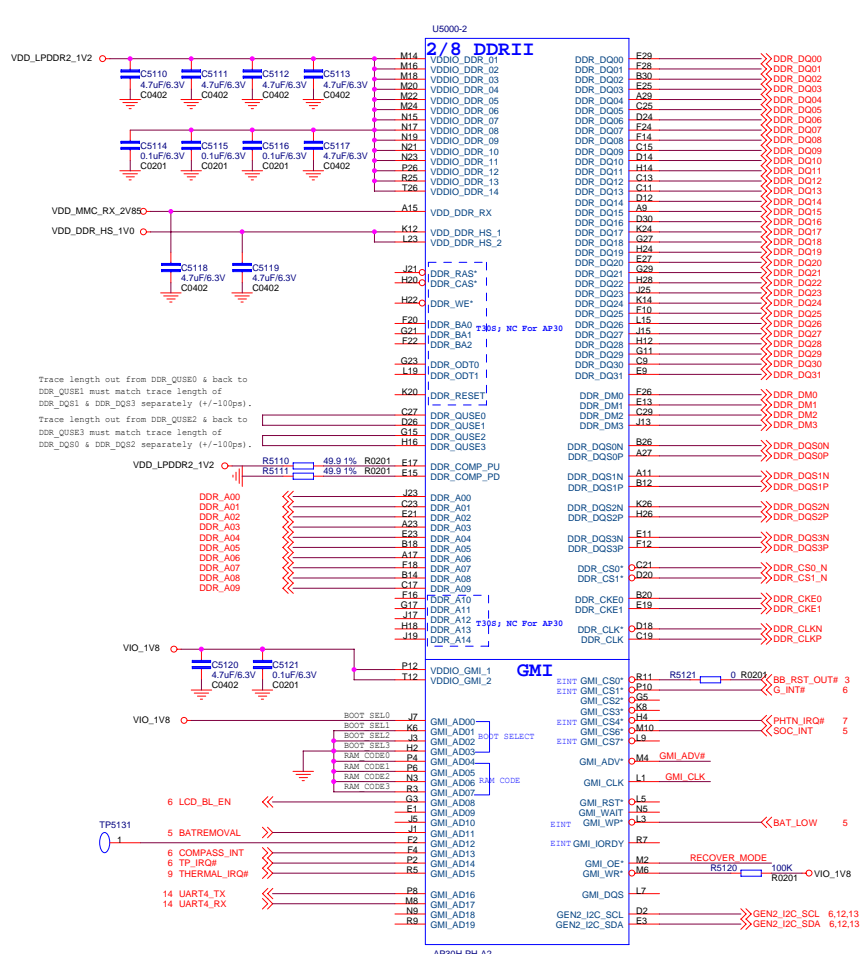
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Title			
AP30 GPIO			
Size	Document Number	Rev	
C		K-Touch V9	
Date:	Friday, August 10, 2012	Sheet	9 of 16



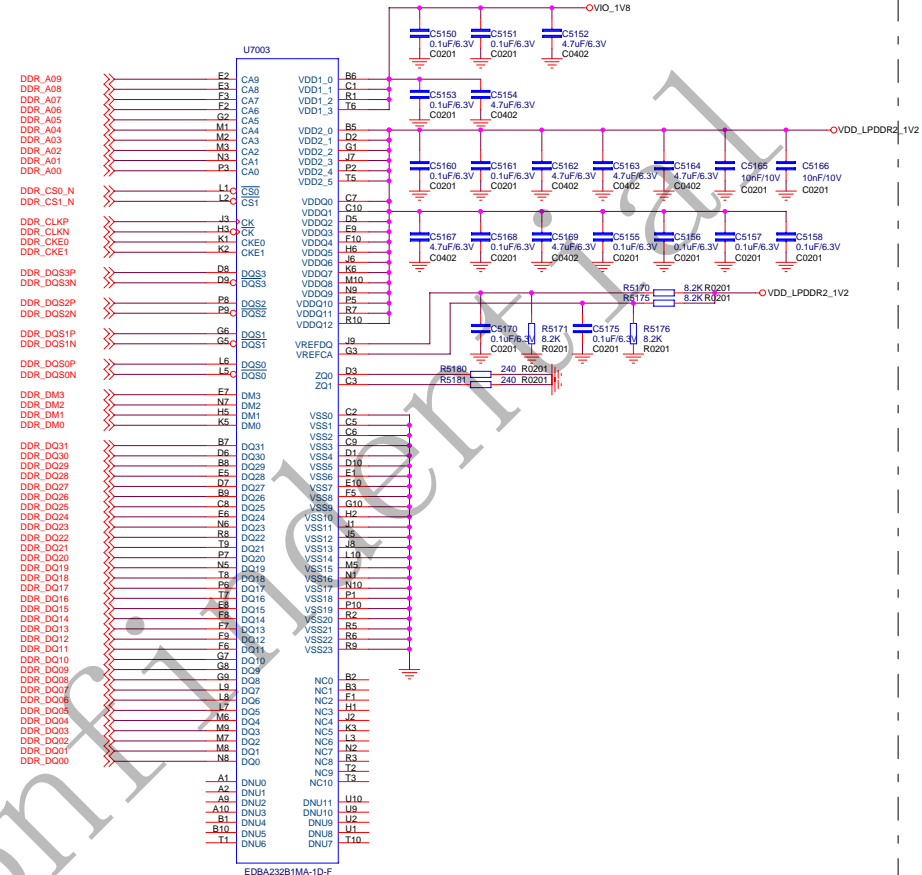
AP30 SDIO INTERFACE



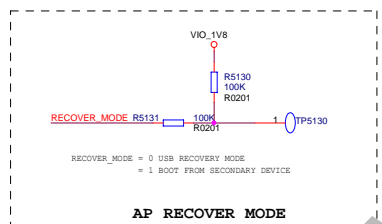
eMMC



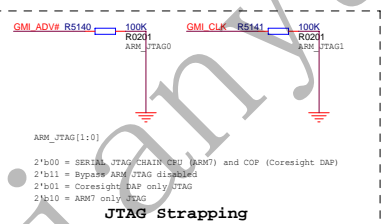
AP30 GMI DDR INTERFACE



DDR



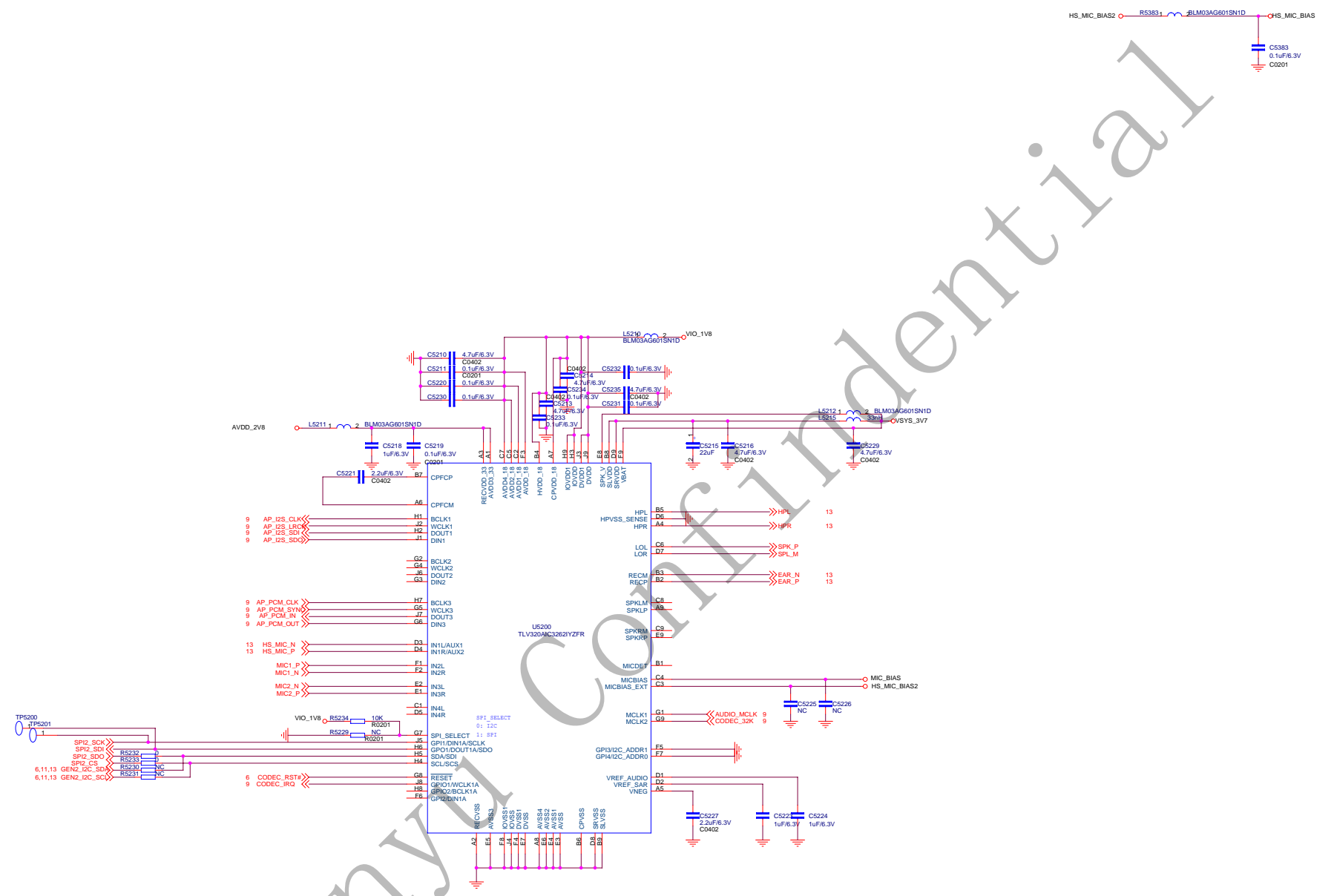
AP RECOVER MODE



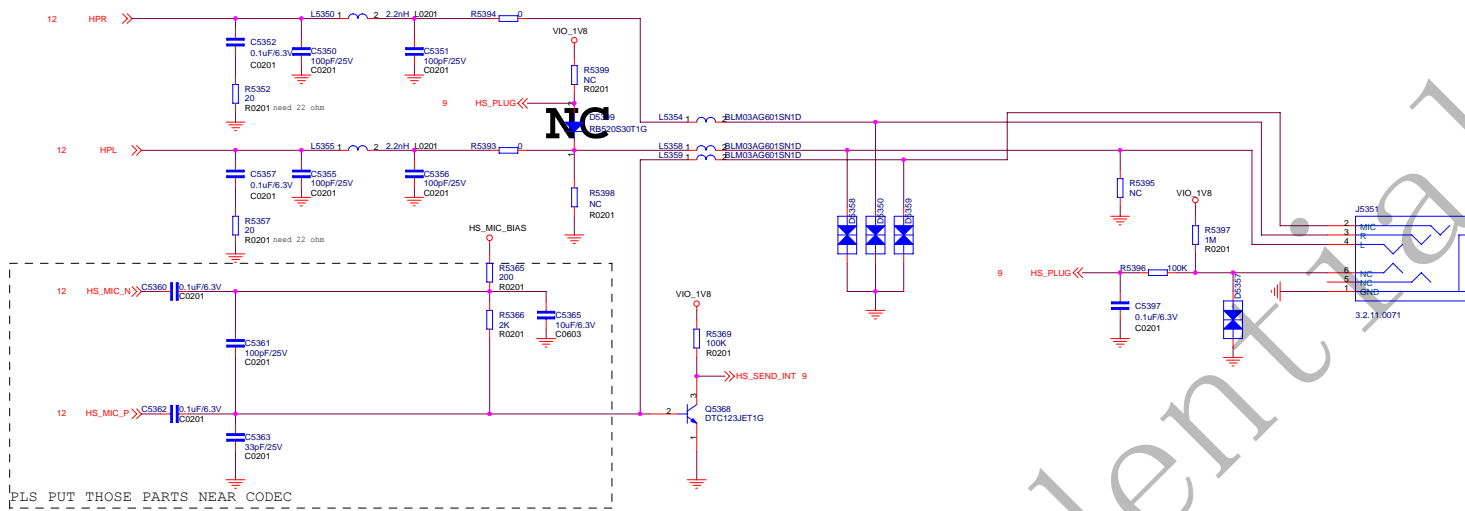
JTAG Strapping



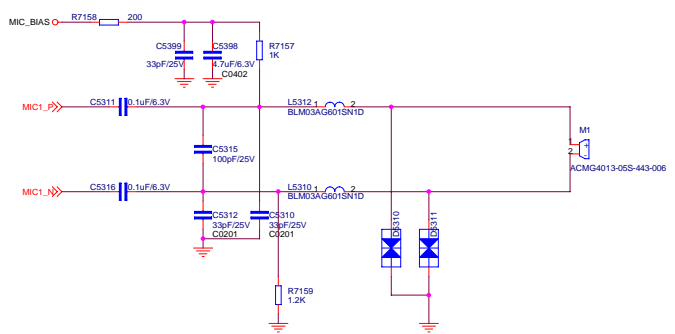
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Title AP30 DDR			
Size C	Document Number	Rev	
K-Touch V9			
Date: Friday, August 10, 2012	Sheet	11	of 16



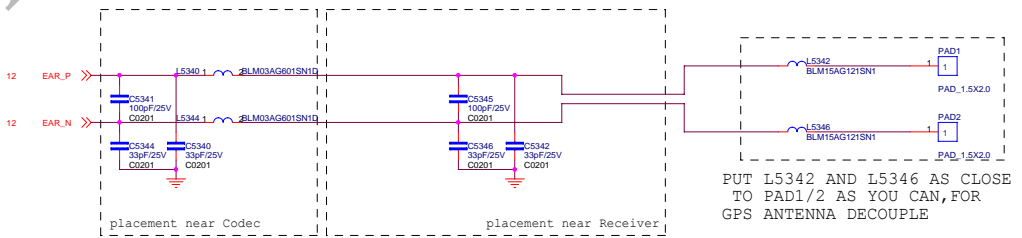
北京天宇朗通通信设备股份有限公司			
File	CODEC		
Size	Document Number	Rev	
A2		K-Touch V9	
Date:	Friday, August 10, 2012	Sheet	12 of 16



Earphone Circuit



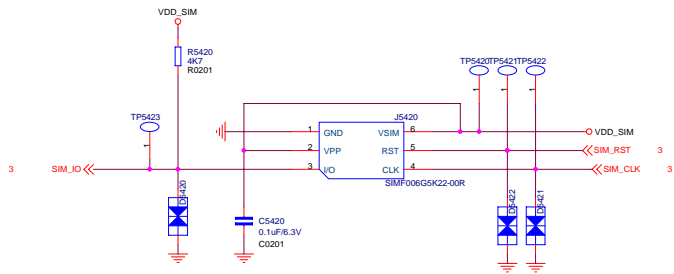
Mic Circuit



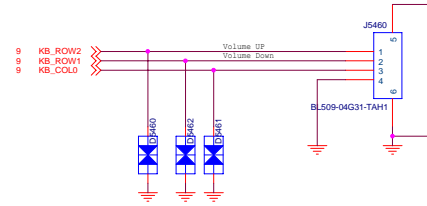
Receiver Circuit

PUT L5342 AND L5346 AS CLOSE TO PAD1/2 AS YOU CAN, FOR GPS ANTENNA DECOUPLE

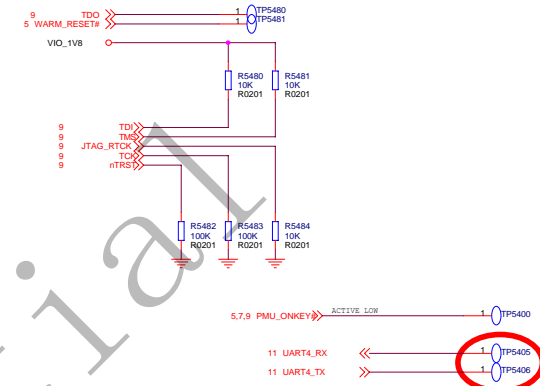
北京天宇朗通通信设备股份有限公司			
AUDIO			
File	Document Number	Rev	
Size	K-Touch V9		
Date	Friday, August 10, 2012	Sheet	13 of 16



SIM CARD

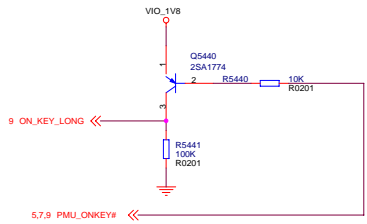


VOLUME KEY

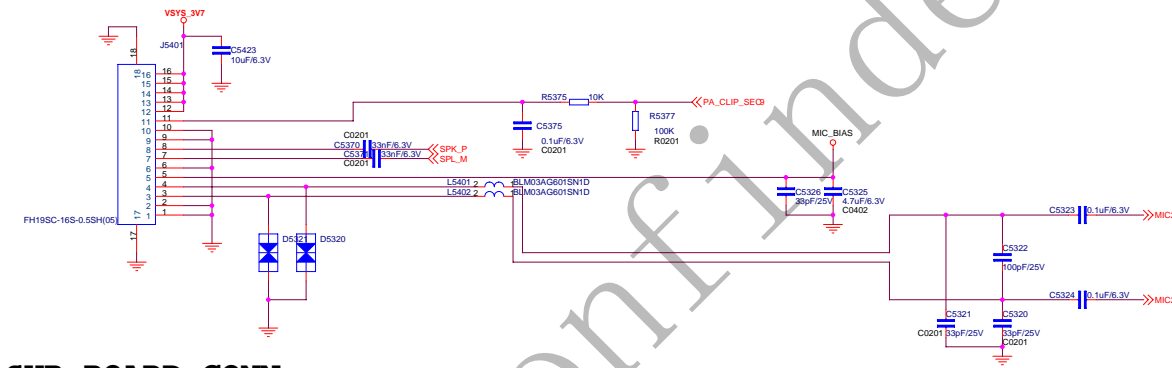


TEST POINT JTAG

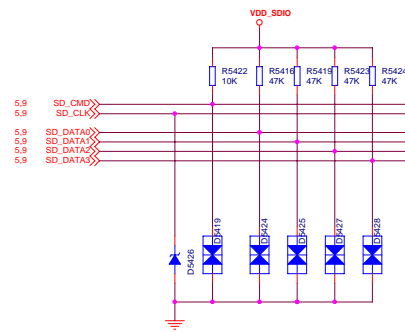
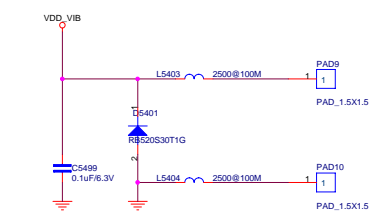
MAKE BOTH OF THEM VISIBLE



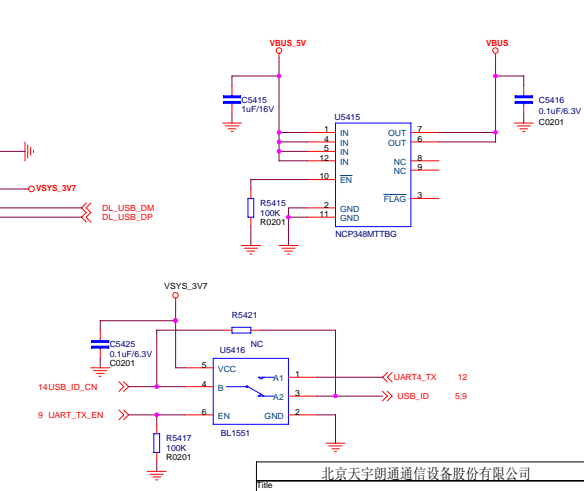
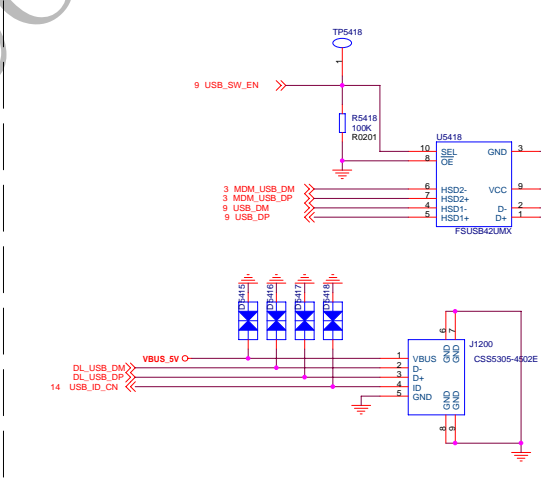
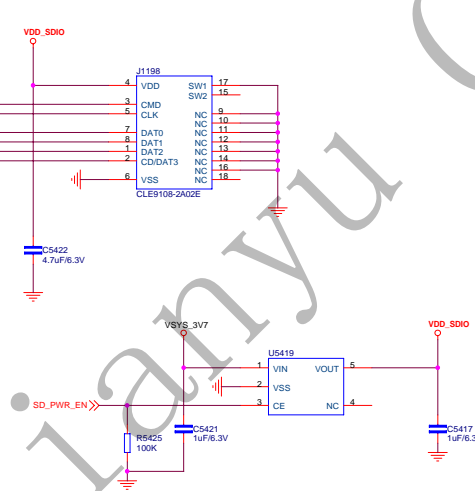
ON KEY SUB BOARD CONN



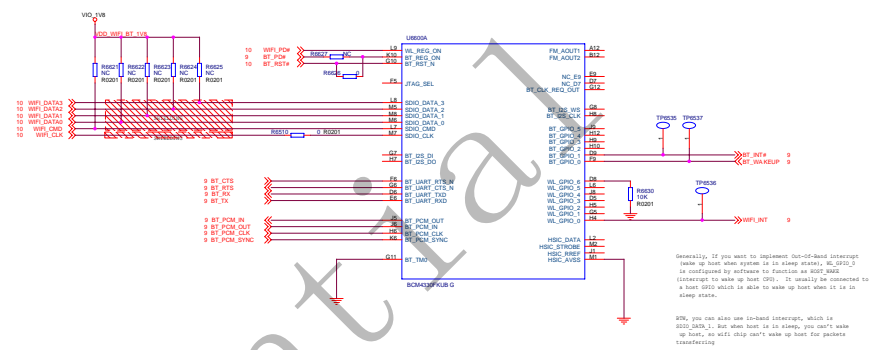
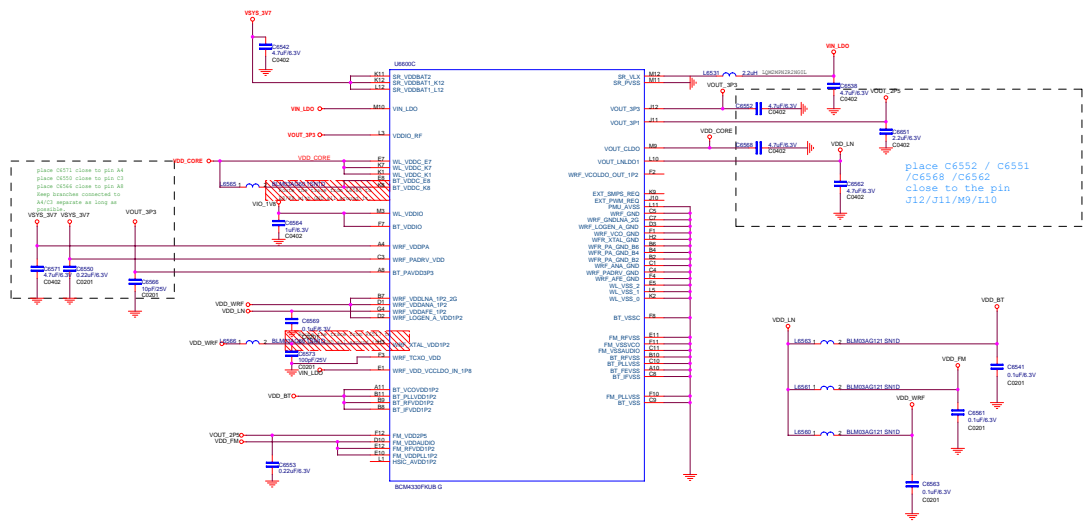
SUB BOARD CONN



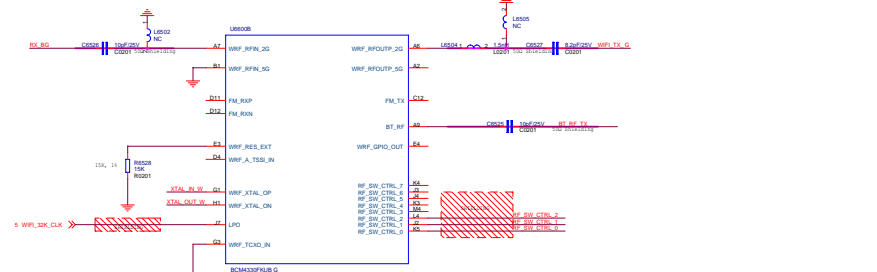
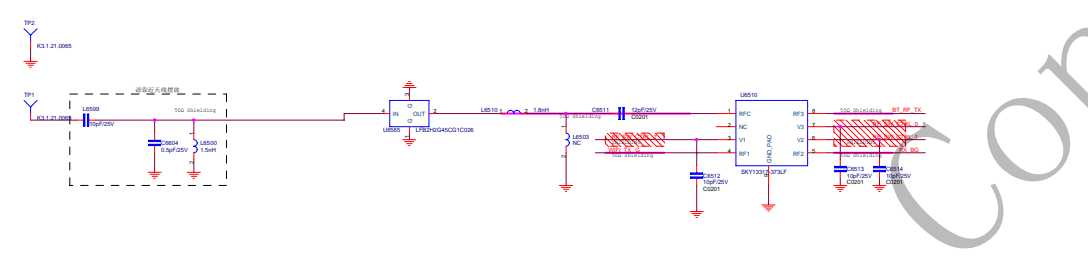
T-FLASH USB INTERFACE



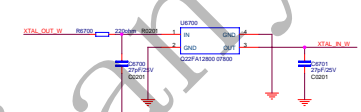
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INTERFACE			
Doc No	Document Number	Rev	
A2			
Date	Friday, August 10, 2012	Sheet	14 of 16



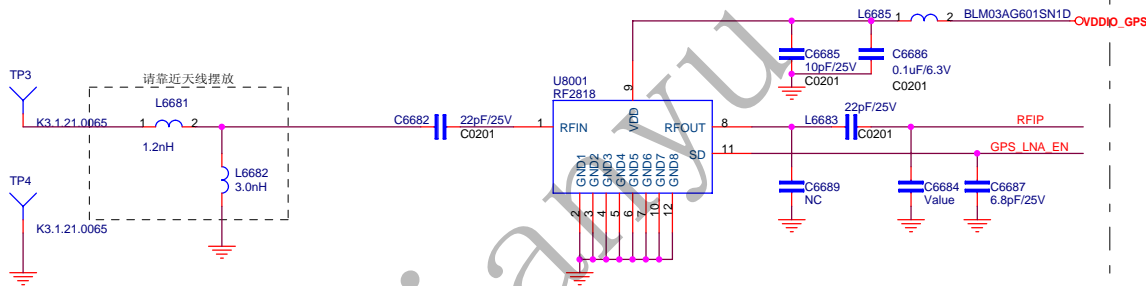
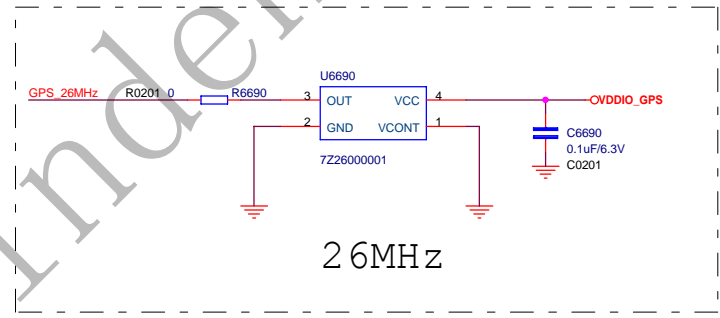
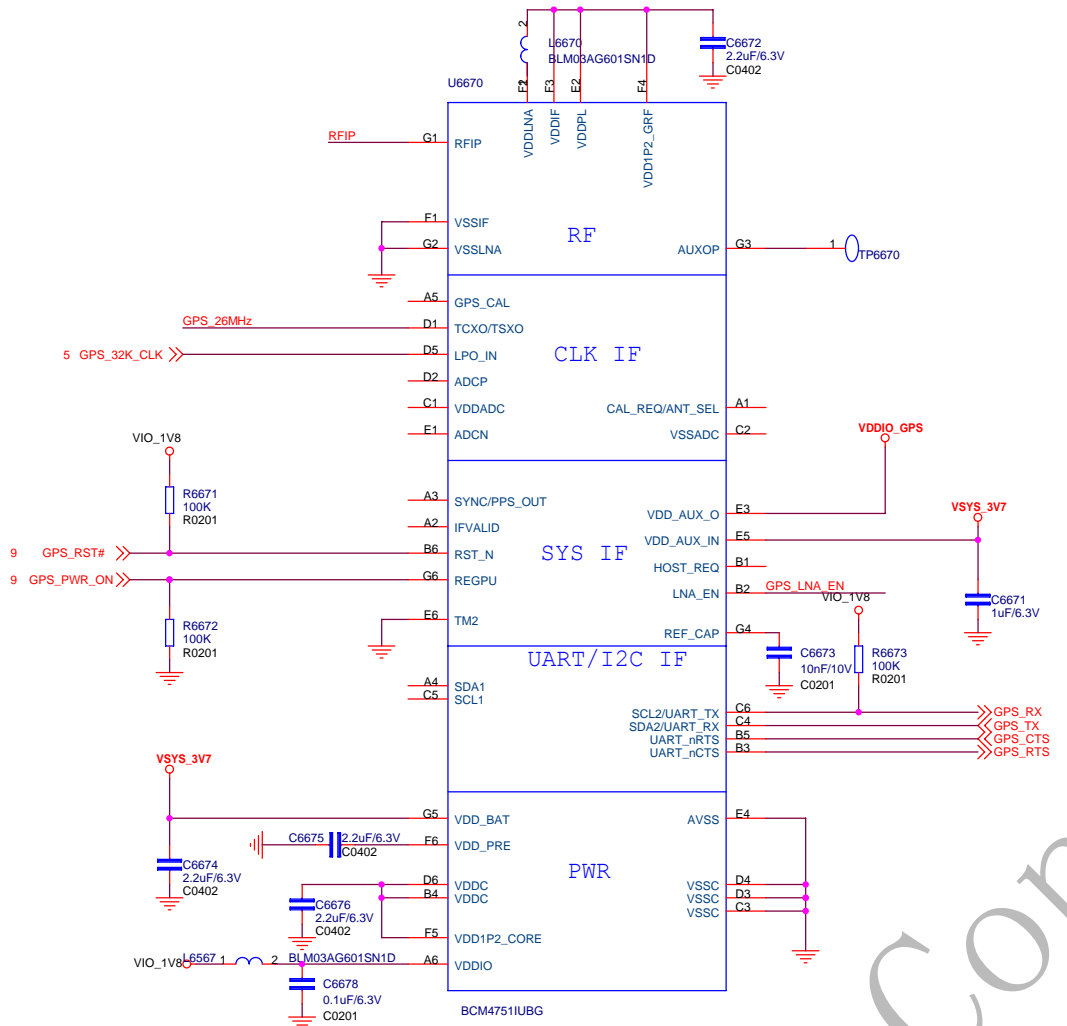
POWER AND LOGIC



POWER AND LOGIC



CRYSTAL



GPS LNA and SAW

北京天宇朗通通信设备股份有限公司		
Title	GPS	
Size	Document Number	Rev
A3	K-Touch V9	
Date:	Friday, August 10, 2012	Sheet 16 of 16

TBW7811 P1 Revision History

0227
 -由“TBW7810_401_100_0227_update”修改
 -删除马达电路
 -删除一个模拟MIC的部分电路，其余部分放到小板连接器旁
 -删除AUDIO PA电路
 -增加16PIN的小板连接器
 -修改LCD连接器，由RGB改为MIPI
 -更换T-Flash卡座
 -更换USB座

0228
 -更改了GPS用TCXO

0229
 -更新了CHIP天线的库
 -修改了主MIC

0301
 -增加R5911

0307
 -修改LCD连接器，TP连接器，LCD filter，电池连接器极性。

0314
 -删除VBUS测试点

0315
 -R5545改成R0402封装
 -修改WIFI
 GPS天线匹配（不改PCB）

0316
 去掉WIFI天线的一个π型匹配。
 C5415换为高度矮的料。

0320
 换R5674的料（不改PCB）
 增加R5722

0321
 换TP6682的料

0322
 更新J1198的库，NC的引脚接地

0515
 仅仅为了CTA修改了每页的页脚，原理部分没有任何变化。

0516
 R5535, R5536改为10K;
 HS_MIC_BIAS连接HS_MIC_BIAS2(R5383, L5383);
 add TP5520, TP5521;
 TP供电改为VDD_LCD_2V8;
 增加U5416及其周边;
 删除U5000.AB30的BAT_GOOD网络;
 C5844 改为22uF, 0805;
 增加R5600;
 修改GAUGE_RESN和GAUGE_RESP的位置
 增加7色灯，增加C5546, D5506, R5547, R5546, Q5502, Q5501
 将电量计处PMU的采样点移到0OHM电阻后端，方便走线

0517
 更改R5593和R5594的封装，由0201改为0402;
 耳机连接器的MIC和地互换;
 PMU_CHRG_DET#与PMU断开，增加TP7399;
 PMU的A4脚接地;

0518
 做AK8975C和MMC3280的兼容设计，增加R5662 R5563 R5564 R5565 C5651
 删除Gyro，增加TP5131
 更改BCM4330的BT_ON和BT_RST设计，增加R6626 R6627
 增加R5643 R5644

0519
 将C5844有Tan电容改为陶瓷电容，封装和容值均不变。
 将L5758改为NC

0810
 增加J5351, R5395, R5397, R5396, C5397, D5357
 将R5399由47K改为NC,
 将D5399改为NC
 将C5353和C5364由100uF改为0 ohm
 增加C5783
 增加R5394和R5393

Confidential

<Variant Name>

Title		
北京天宇朗通信设备股份有限公司 Revision History		
Size A4	Document Number TBW7808	Rev 1.0
Date:	Friday, August 10, 2012	Sheet 18 of 18